

AD-A111 491

IBM FEDERAL SYSTEMS DIV MANASSAS VA

F/G 9/2

ELECTRICAL CHARACTERIZATION OF THE 68000 MICROPROCESSOR.(U)

F30602-80-C-0119

DEC 81 J D BAILEY

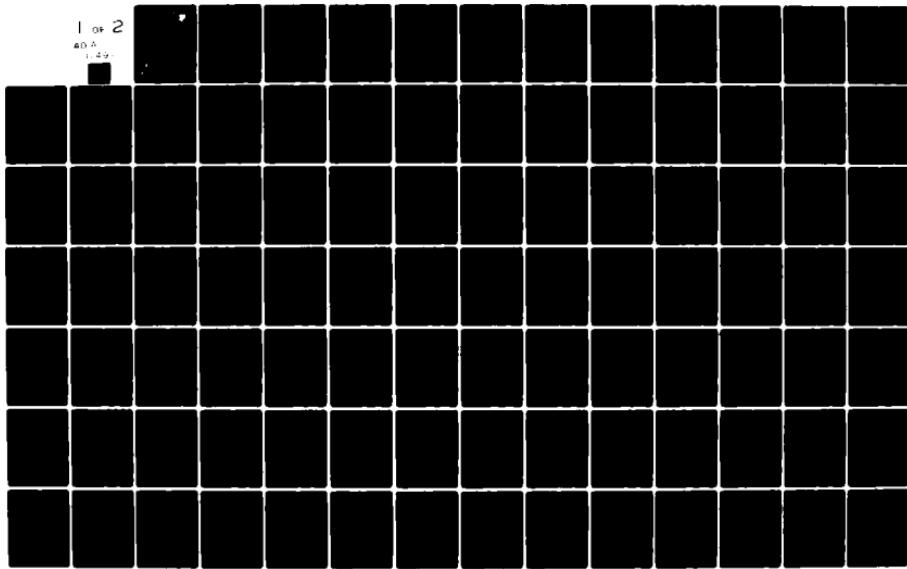
RADC-TR-81-350

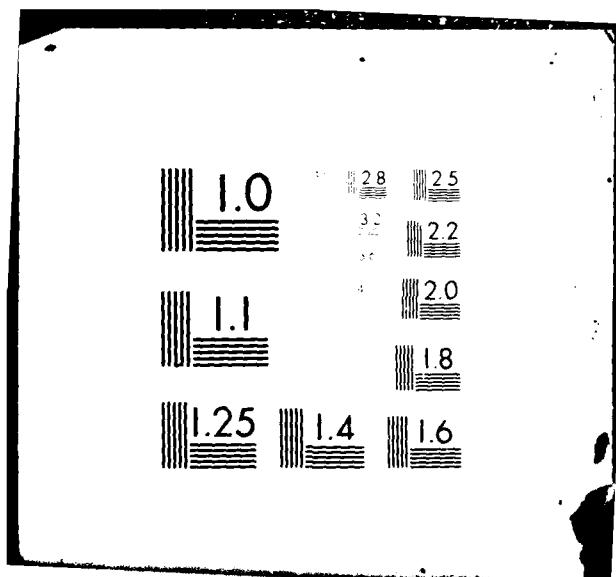
NL

UNCLASSIFIED

1 OF 2

ADA
1-4-2





ADA111491

RADC-TR-81-350
Final Technical Report
December 1981

110
D2



ELECTRICAL CHARACTERIZATION OF THE 68000 MICROPROCESSOR

IBM Corporation

Jim D. Bailey



APPROVED FOR PUBLIC RELEASE; DISTRIBUTION UNLIMITED

ROME AIR DEVELOPMENT CENTER
Air Force Systems Command
Griffiss Air Force Base, New York 13441
FILE #

This report has been reviewed by the RADC Public Affairs Office (PA) and is releasable to the National Technical Information Service (NTIS). At NTIS it will be releasable to the general public, including foreign nations.

RADC-TR-81-350 has been reviewed and is approved for publication.

APPROVED:

REGIS C. HILOW
Project Engineer

APPROVED:

EDMUND J. WESTCOTT
Technical Director
Reliability & Compatibility Division

FOR THE COMMANDER:

JOHN P. HUSS
Acting Chief, Plans Office

If your address has changed or if you wish to be removed from the mailing list, or if the addressee is no longer employed by your organization, please notify RADC (RBRA) Griffiss AFB NY 13441. This will assist us in maintaining a current mailing list.

Do not return copies of this report unless contractual obligations or notices on a specific document requires that it be returned.

UNCLASSIFIED

SECURITY CLASSIFICATION OF THIS PAGE (When Data Entered)

REPORT DOCUMENTATION PAGE		READ INSTRUCTIONS BEFORE COMPLETING FORM
1. REPORT NUMBER RADC-TR-81-350	2. GOVT ACCESSION NO. ED-A111 1/91	3. RECIPIENT'S CATALOG NUMBER
4. TITLE (and Subtitle) ELECTRICAL CHARACTERIZATION OF THE 68000 MICROPROCESSOR		5. TYPE OF REPORT & PERIOD COVERED Final Technical Report Apr 80 - Oct 81
		6. PERFORMING ORG. REPORT NUMBER N/A
7. AUTHOR(s) Jim D. Bailey		8. CONTRACT OR GRANT NUMBER(s) F30602-80-C-0119
9. PERFORMING ORGANIZATION NAME AND ADDRESS IBM Corporation Manassas VA 22110		10. PROGRAM ELEMENT, PROJECT, TASK AREA & WORK UNIT NUMBERS 62702F 2338011E
11. CONTROLLING OFFICE NAME AND ADDRESS Rome Air Development Center (RBRA) Griffiss AFB NY 13441		12. REPORT DATE December 1981
		13. NUMBER OF PAGES 124
14. MONITORING AGENCY NAME & ADDRESS(if different from Controlling Office) Same		15. SECURITY CLASS. (of this report) UNCLASSIFIED
		15a. DECLASSIFICATION/DOWNGRADING SCHEDULE N/A
16. DISTRIBUTION STATEMENT (of this Report) Approved for public release; distribution unlimited.		
17. DISTRIBUTION STATEMENT (of the abstract entered in Block 20, if different from Report) Same		
18. SUPPLEMENTARY NOTES RADC Project Engineer: Regis C. Hilow (RBRA)		
19. KEY WORDS (Continue on reverse side if necessary and identify by block number) Microprocessor Software Electrical Testing Test Methods		
20. ABSTRACT (Continue on reverse side if necessary and identify by block number) This document discusses in detail the electrical characterization of the Motorola 68000, 16 bit microprocessor. Test results are presented on various mask sets and production lots. The test philosophy and test programs that were developed in this study are also presented in sufficient detail..		

UNCLASSIFIED

SECURITY CLASSIFICATION OF THIS PAGE(When Data Entered)

UNCLASSIFIED

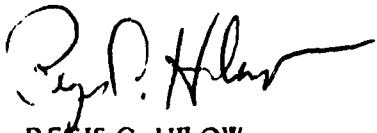
SECURITY CLASSIFICATION OF THIS PAGE(When Data Entered)

EVALUATION

The objective of this effort was to electrically characterize the 68000, 16 bit microprocessor. From the resulting data, a MIL-M-38510 detail specification was to be prepared in a format compatible with DOD coordination standards.

The electrical characterization of the 68000 was successfully accomplished through a very complex and time consuming task. Over the course of this program, this state-of-the-art microprocessor was updated several times by the vendor to enhance performance and/or to improve yields. Each change required a thorough evaluation and comparison of the design or process enhancements versus potential reliability degradation. IBM produced a military detail specification M38510/540 to cover the latest update of the 68000. This specification defines three versions of the 68000 categorized by frequency and enclosed in three package types including two state-of-the-art leadless chip carrier packages.

This program demonstrates what can be accomplished when there exists a good working relationship between the user and the manufacturer of the part. IBM took a basic commercial part and provided the manufacturer the data he needed to militarize it. Motorola on the other hand cooperated in providing information, some proprietary, on key architectural and circuit designs, in addition to information on processing enhancements.


REGIS C. HILOW
Project Engineer



Accession For	
NTIS GRA&I	<input checked="" type="checkbox"/>
DTIC TIB	<input type="checkbox"/>
Unannounced	<input type="checkbox"/>
Justification	<input type="checkbox"/>
By _____	
Distribution/	
Availability Codes	

14

TABLE OF CONTENTS

<u>Section No.</u>		<u>Page</u>
i	List of Figures and Illustrations	vii
ii	List of Tables	ix
1.0	Introduction	1
2.0	Device Description	2
3.0	Electrical Characterization Program Development	7
4.0	Device Evaluation	21
5.0	Conclusion	52
Appendix A Instruction Decode Software Description		
Appendix B MC68000 Characterization Run		
Appendix C General Parametric Plots		

PRECEDING PAGE BLANK-NOT FILMED

LIST OF FIGURES AND ILLUSTRATIONS

<u>Figure</u>		<u>Page</u>
1.0	MC68000 Block Diagram	3
2.0	Signal Pin Description	4
3.0	Output Load Circuit	14
4.0	ICC vs Temperature (MC68000L10)	37
5.0	ICC vs Temperature (MC68000-L10-L8X)	44
5.1	TCH vs Temperature (MC68000L8-L10-L8X)	45

PRECEDING PAGE BLANK-NOT FILMED

LIST OF TABLES

<u>Table</u>		<u>Page</u>
1.0	Measured AC Delays	9
2.0	Derived AC Delays	10
3.0	Measured DC Parametric Tests	11
4.0-4.5	T6E Fail Test Summary	15
5.0-5.2	MC68000L8 Functional Summary	23
5.3	MC68000L8 DC Test Summary	27
5.4-5.5	MC68000L8 AC Test Summary	28
6.0-6.2	MC68000L10 Functional Summary	31
6.3	MC68000L10 DC Test Summary	34
6.4	MC68000L10 AC Test Summary	35
7.0-7.2	MC68000L8 (Late Version) Functional Summary	38
7.3	MC68000L8 DC Test Summary	41
7.4	MC68000L8 AC Test Summary	42
8.0-8.2	HD68000 Functional Summary	46
8.3	HD68000 DC Test Summary	49
8.4	HD68000 AC Test Summary	50

PRECEDING PAGE BLANK-NOT FILMED

1.0 INTRODUCTION

The MC68000 is one of the most technologically advanced and architecturally superior microprocessors available today. It follows that an acceptable electrical evaluation of this device would be a complex and time consuming task. This document will discuss in detail the MC68000 Electrical Characterization program and the results that were obtained as various mask sets and device lots were tested across an extended temperature range. For additional information on device description and system integration the reader should reference the Motorola Users Guide MC68000UM (AD2).

At the outset it must be noted that no MIL-883B type part was available for this test exercise from Motorola. Due to the recent announcement and frequent performance enhancements, a military device is now feasible. This program supports the accelerated development of that military product. Early functional failures at the MIL- temperature extremes are noted in this report and are to be expected since these devices were not screened to those corners. As the report tracks the maturity of the masks and process, the functionality at the temperature extremes improved greatly, yielding over 80% fully functional devices (of the test samples) to the military specification generated.

2.0 DEVICE DESCRIPTION

2.1 TECHNOLOGY

The MC68000 is a single chip 16-bit microprocessor fabricated using an N-channel, depletion load, silicon gate technology. The die, measuring approximately $40 \mu\text{m}^2$ contains approximately 70,000 transistors. This level of density was achieved with the use of $3\mu\text{m}$ ground rules (HMOS I).

Further enhancements (HMOS II) and shrinkage is expected in 1982.

2.2 BLOCK DIAGRAM

A block diagram of the MC68000 is shown in Figure 1.0. The processor is composed of seventeen 16-bit registers, a program counter, status register, 16-bit ALU and control section. The flexible instruction set consisting of 56 instructions and 14 different addressing modes is implemented using an on-board microcode ROM. In addition the processor control section will support direct memory access, seven levels of processor peripheral interrupt and 6800 peripheral interface control. The 23 address lines that are supported by the processor allow direct access to over 16 M bytes of memory.

2.3 PIN DESCRIPTION

The MC68000 signal and pin assignment diagram is shown in Figure 2.0.

2.3.1 Address Bus

The address bus is composed of 23 tri-state bus outputs which provide addressing for all bus cycles except DMA operations and interrupts. The 23-bit address range of the processor allows addressing of over 8 MWords (16-MBytes) of memory.

2.3.2 Data Bus

The data bus is a 16-bit, bi-directional, tri-state path for data flowing to and from the processor. Data can be in byte or word length.

2.3.3 Address Strobe (AS)

The address strobe is an active low unidirectional tri-state signal. When AS is low it indicates that the address present on the address pins of the processor is valid.

2.3.4 READ/WRITE (R/W)

The READ/WRITE pin is a unidirectional tri-state signal that defines the processor operation and data bus direction. The signal is low (logic 0) during processor write operations and is high (logic 1) for all subsequent processor operations.

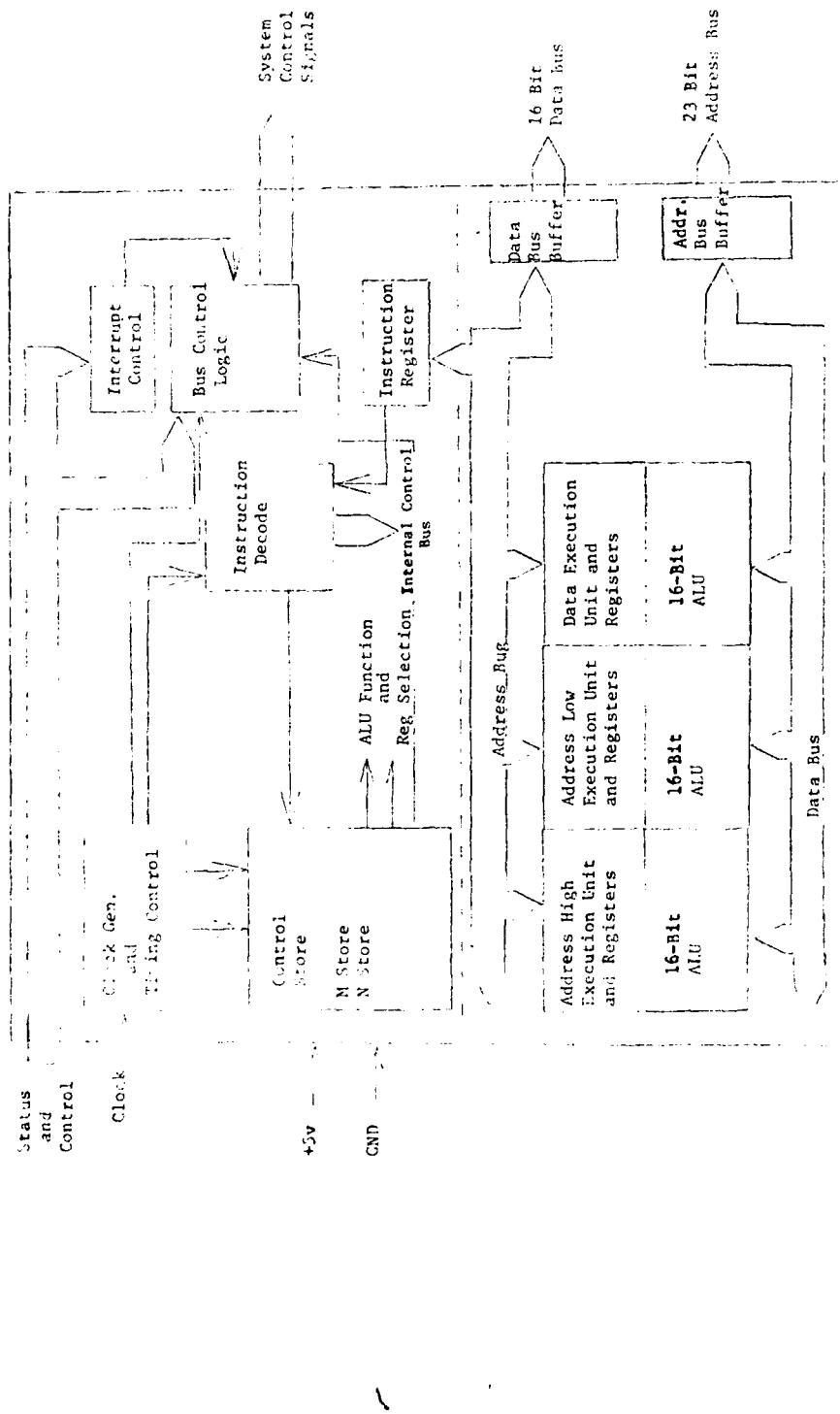


Figure 1.0 MC68000 Block Diagram

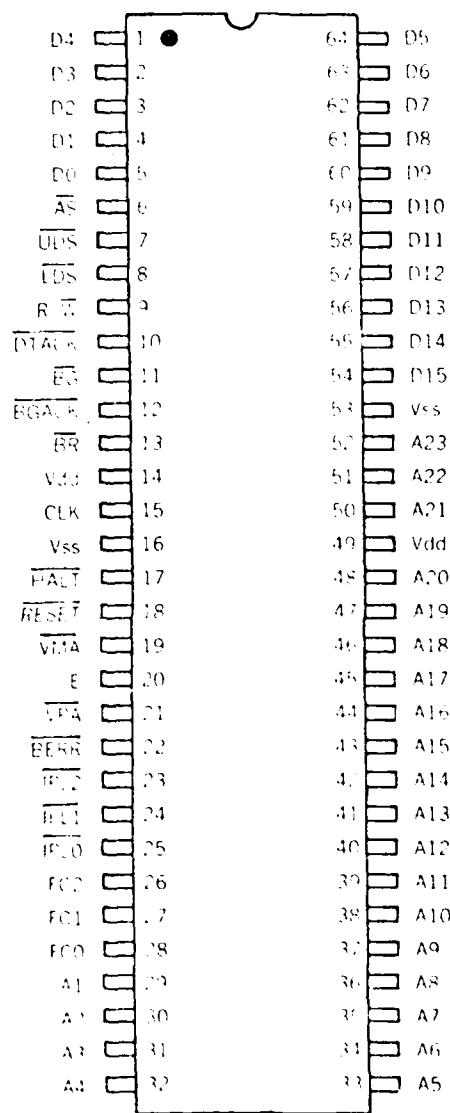


Figure 2.0 Terminal Connection and Pin Assignment

2.3.5 Upper and Lower Data Strobes (UDS-LDS)

The UDS and LDS are active low unidirectional control signals that indicate which half (upper 8 bits -UDS, lower 8 bit -LDS) are valid on the data bus during processor write operations. The UDS and LDS will always be active during processor read operations.

2.3.6 Data Transfer Acknowledge (DTACK)

The DTACK input is an active low asynchronous control line used to signal the CPU that a particular bus operation has been completed. The DTACK input is recognized by the processor on the falling edge of the input clock during CPU READ/WRITE operations. In early mask set devices (R9M, T6E) if DTACK was active by the fall of the input clock during bus cycle two (for READ/WRITE) the particular operation would be shortened by one CLK cycle. In later mask set devices (CCL) if DTACK is active at the fall of the input clock during bus cycle two it will have no effect on the overall bus operation.

2.3.7 Bus Request (BR)

This active low unidirectional input is used to signal the CPU that some other device wishes to take control of the system bus.

2.3.8 Bus Grant (BG)

The active low unidirectional output is used to signal other potential bus masters that the CPU will release the bus following completion of the current bus operation.

2.3.9 Bus Grant Acknowledge (BGACK)

This active low unidirectional input is used to signal the CPU that another device has control of the system bus.

2.3.10 Interrupt Control (IPL0, IPL1, IPL2)

These three active low unidirectional inputs are used by other devices that request a CPU interrupt. The three inputs allow seven levels of prioritized interrupts with level zero being the lowest priority.

2.3.11 Bus Error (BERR)

This active low unidirectional input is used to signal the CPU when a problem has occurred during a bus operations. It is used in conjunction with HALT to determine if the operation should be retried or the processor should initiate exception processing.

2.3.12 Reset

This bi-directional active low signal is used in conjunction with the HALT line to reset the CPU (system initialization sequence). In addition it is used to reset peripheral devices (see reset instruction).

2.3.13 HALT

The active low bi-directional signal is used to halt the processor at the end of a current bus cycle or to indicate the processor has halted due to a system failure.

2.3.14 Enable (E)

The unidirectional tri-state output is used to synchronously interface M6800 peripheral devices with the MC68000. The E output is a divide by ten of the input clock. The state of E output cannot be determined following a power on reset sequence.

2.3.15 Valid Peripheral Address (VPA)

This active low unidirectional input indicates that the device being addressed and the subsequent data transfer should be synchronized to the MC68000 by the use of the E signal. If active low during an interrupt this signal indicates to the processor that auto vectoring should be used.

2.3.16 Valid Memory Address (VMA)

This active low unidirectional output indicates that the address on the bus is valid and that the device being addressed (M6800) is in sync with the processor.

2.3.17 Processor Status (FC0, FC1, FC2)

These three unidirectional tri-state output signals indicate the state of the present processor operation (user or supervisor) and the type cycle being executed.

2.3.18 CLOCK (CLK)

This unidirectional input is the primary processor clock. The clock input waveform should be a signal having a 50% duty cycle and vary in frequency from 3 MHZ to 10 MHZ.

2.3.19 Signal Summary

All MC68000 signals are TTL compatible signals. The signal descriptions given in this section have been abbreviated and serve to familiarize the reader with the device and to point out some areas of interest that were discovered during characterization and are not mentioned in the vendors users guide. A more detailed description of the device pins and their function can be found in the Motorola Users Guide MC68000UM (AD2).

3.0 ELECTRICAL CHARACTERIZATION PROGRAM DEVELOPMENT

3.1 TEST EQUIPMENT

Due to the complexity of the MC68000 and the asynchronous bus structure of the device, an extensive amount of hardware was necessary in order to develop the function test vectors that would be used during the device characterization. The hardware included:

- o In-house 16-bit Proto-typing System
- o MDS-800 Development System
- o HP 1615A Logic Analyzer
- o IBM System S/370 (Editor)
- o Macrodata MD-501 LSI Tester

The procedure for developing the software was to load a MC68000 test program into the proto-type system using the MDS-800 Development System. The program was then executed and the device outputs monitored using the H.P. 1615A Logic Analyzer. After determining the sequence in which the processor executed the program, the assembly code necessary to generate the Binary tester pattern for each clock cycle of execution was entered and properly coded with the aid of an IBM S/370 editor. The software was then downlinked to magtape and transferred to the Macrodata MD-501 LSI tester for final compilation and assembly into a Binary format. All device testing (functional, AC and DC) was performed using the MD-501. The Macrodata MD-501 is a 10 MHZ, 64 channel LSI tester. All 64 channels can be configured as either input, output or as a power supply. All power supplies are accurate to within 0.1% of their programmed value. All AC measurements are accurate to within ± 1ns.

3.2 Functional Testing

3.2.1 Logic Block Element Testing

Functional test software development was broken into two categories. The first category was Logic Block Element Testing (LBET). The objective was to stimulate the various logic sections of the device using a minimum number of instructions to insure that each of the relatively large functional blocks were operational, prior to instituting the very long and detailed instruction decode verification testing. The categories to be tested were:

- o Reset
- o Register, Array
- o PC Test
- o ALU
- o Stack Test
- o Interrupts

The reset test verifies the power-on reset sequence and the reset and halt instructions are operational.

The register array test ensures the integrity of each of the data and address registers. Pattern sensitive data is loaded into each register and checked for proper loading. In addition all other registers are tested for any possible adjacent register disturbance.

The objective of the ALU test is to insure functionality of the ALU. This is accomplished by executing all arithmetic and logical operations and testing the resulting output.

The PC and stack test verify operation of the program counter and supervisor stack pointer, by incrementing and where feasible decrementing each counter through overflow or underflow.

The interrupt test verifies the processor will respond to all levels of interrupt and that the proper interrupt vector location is executed for each level of interrupt.

3.2.2 Instruction Decode

The level of complexity of the MC68000 (56 instructions and 14 different addressing modes) makes testing of all instructions a very lengthy process. The approach to instruction testing was to break the instruction set into six categories. These categories were:

- o Data movement
- o Arithmetic operations
- o Shift, rotates and logicals
- o BCD operations
- o Bit Test Operations
- o Program/System Control

A detailed description of each program and the opcodes tested are given in Appendix A. When the functional test programs are converted to the conventional (Binary) format the result was over 13,000 lines of executable code. Due to the length of the Binary patterns they are not included within this document. However, they can be obtained from Rome Air Development Center (RADC) Reliability Branch. These patterns represent the forced and expected data by clock cycle for the automatic test equipment stimulation (MD-501) of the MC68000 device.

3.3 A.C. PERFORMANCE TEST DEVELOPMENT

The primary objective of the AC Test Development was to measure all of the most critical delays that are associated with the MC68000. The functional test patterns were used to precondition the device to a known state prior to performing the required measurement. The baseline used to determine which delays would be measured was the vendors data sheet. The delays shown in Table 1.0 are the actual delays that are measured using the MD-501. All measured times are accurate within \pm 1ns. Due to the enable output (E) being in an undetermined state after power-on reset it was necessary to obtain the

Table 1.0

AC PERFORMANCE - SPECIFICATION - MULICO					
TEST	SYMBOL	EG	EG+	NOTES	CONDITIONS
ACR VALID TO ACR INVLD	TAVN	1	11	NS	DRIVER LOGIC
ANALOG TO ANALOG INVLD TEST					
ANALOG TO ANALOG INVLD TEST	TAVZ	1	13	NS	
ANALOG WIDTH LOW	TAFL	1	19	NS	
ANALOG WIDTH HIGH	TAFH	1	25	NS	
DS HIGH TO DS HIGH	TSHDH	1	17	NS	
DS LOW TO DS LOW	TSHL	1	21	NS	
DS LOW TO DS LOW	TRSHL	1	22	NS	
DS HIGH TO DS INVLD	TSHDQ	1	25	NS	
DS H TO DS INVLD TEST	TSHDQ	1	29	NS	
DS LOW TO EG LOW	TEREL	1	25	CLKS	
EG HIGH TO EG HIGH	TEHGH	1	30	CLKS	
EGS LOW TO EG HIGH	TEGAHG	1	37	CLKS	
EGS LOW TO DS TEST	TEGZ	1	38	CLKS	
EG WIDTH HIGH	TEGH	1	39	CLKS	
VMS LOW TO E HIGH	TVMLEH	1	43	CLKS	
CSAS HIGH TO VPA HIGH	TSHPHN	1	44	NS	
E LOW TO ACR INVLD	TELAT	1	45	NS	
EACK WIDTH	TEBL	1	46	CLKS	
PERM LOW TO EACK LOW	TERDLC	1	48	NS	
E WIDTH HIGH	TEH	1	50	NS	
E WIDTH LOW	TEL	1	51	NS	

Table 2.0

TEST	SYMBOL	CONDITIONS	UNITS	TEST	COMMENTS
				TEMP.	
					CODE
I _{CC} TEST	I _{CC}	V _{CC} = 5.5V	MA		V _{CC} = 5.5VOLTS
V _O L A23-1,FC0-2,BGxE	V _O L	I _{OL} = 3.2MA	VOLTS		V _{CC} = 4.5VOLTS
V _O L HALT	V _O L	I _{OL} = 1.6MA	VOLTS		"
V _O L AS,R/W,D15-0 UDS,LDS,VMA	V _O L	I _{OL} = 5.3MA	VOLTS		"
V _O L RESET	V _O L	I _{OL} = 5.0MA	VOLTS		"
V _O H (ALL OUTPUTS)	V _O H	I _{OH} = 400UA	VOLTS		
I _{TH} (ALL INPUTS)	I _{TH}	V _{TH} = 2.4 VOLTS	UA		
I _{TI} (ALL INPUTS)	I _{TI}	V _{TI} = 0.4 VOLTS	UA		
I _{OHZ} (ALL OUTPUTS)	I _{OHZ}	V _{OH} = 2.4 VOLTS	UA		
I _{OULZ} (ALL OUTPUTS)	I _{OULZ}	V _{OL} = 0.4 VOLTS	UA		
V _{TH} (ALL INPUTS)	V _{TH}	VGS TEST	VOLTS		V _{CC} = 4.5
V _{TL} (ALL INPUTS)	V _{TL}		VOLTS		V _{CC} = 4.5

Table 3.0

test mode for syncing the E output from Motorola. This information is considered proprietary and thus cannot be disclosed in this document. The delays shown in Table 2.0 are referred to as derived delays. These delays are output to output delays and are not directly measured by the MD-501 but are calculated based upon data obtained from the measured delays. Additional delays not specified by the vendor were measured and used to calculate these output to output delays.

The output loads used during AC testing were based upon the vendors recommended load circuit. The output load circuits are shown in Figure 3.0. A modification to the vendors load circuit was required to properly measure the tri-state delays. In Figure 3.0 the resistor Rx was added during tri-state measurements only. The resistor Rx when in parallel with R₁ will make the pull-down resistance equal to the pull-up resistance (R_n). This will result in the outputs which are at a high level (logic 1) prior to tri-stating having the same tri-state fall transition as the rise time of the outputs which are at a low level (logic 0) prior to tri-stating. Without this loading change fall times exceed 2 to 3 clock cycles of decay (fall) time and are immeasurable by most modern ATE.

3.4 DC PARAMETRIC TEST DEVELOPMENT

The D.C. tests developed to evaluate the MC68000 are shown in Table 3.0. The baseline for test development was the vendors data sheet. I_{cc} was measured dynamically (device running). In all tests V_{cc} was set to worse case. It was necessary to use the special tester configuration to sync Enable (E) and (VMA) outputs for D.C. measurements. All other test conditions were obtained from the vendors data sheet.

3.5 MAXIMUM OPERATING FREQUENCY (FMAX) TEST DEVELOPMENT

Due to the very high operating frequency (Fmax) of the MC68000 (8 MHZ - 10 MHZ) it was necessary to develop a method of determining the High Frequency limit of device operation. The exchange functional test pattern was used to implement an FMAX test. The FMAX test insures the MC68000 is operating correctly for the following frequencies:

- o 4.0 MHZ
- o 5.8 MHZ
- o 7.14 MHZ
- o 7.7 MHZ
- o 8.3 MHZ

The upper limit is the maximum that could be achieved by the 10 MHZ MD-501.

3.6 CHARACTERIZATION PROGRAM SUMMARY

The finalized characterization program used to evaluate the MC68000 consisted of all the previously described tests except the LBET which is used for preliminary verification on development products only. Each test block

was varied by frequency, and/or Vcc variations as necessary to determine the MC68000 operability limitations. The test compendium is repeated at -65°C, 25°C and +110°C case temp. A brief summary of the specified test variations follows.

All DC tests were measured at worse case supplies. All functional tests were executed at two frequencies (2.0 - 2.88 MHZ) with Vcc = 4.5v-5.5v. The FMAX test was performed at Vcc = 4.5v -5.5v. All AC performance measurements were made with Vcc = 5.0v and an operating frequency of 2 MHZ. Shown in Appendix B is a sample test run of the MC68000 characterization program.

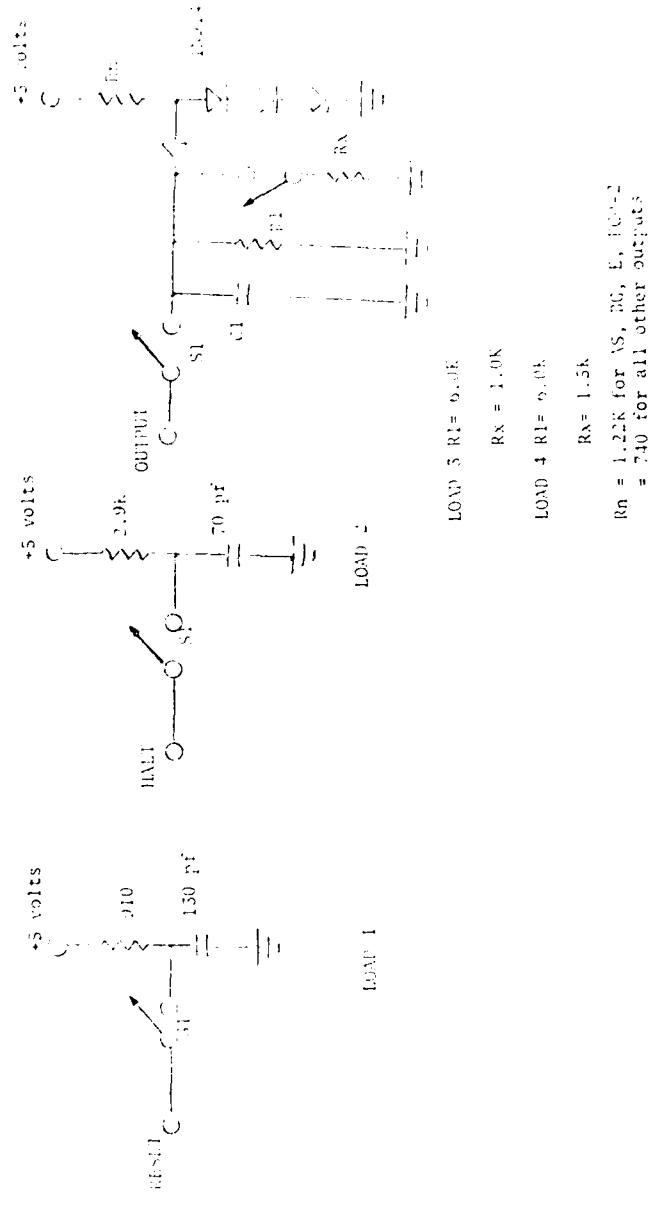


Figure 3.0 Output Load Circuit

T6E Device Functional Fail Summary

TEST	Vcc I	Vcc @ 1MHz	Vcc @ 2.0MHz	Vcc @ 2.85MHz	COMMENTS
		4.5 4.75 5.0 5.25 5.5	4.5 4.75 5.0 5.25 5.5	4.5 4.75 5.0 5.25 5.5	
RESET	-55				
	+25				
	+100	X X	X	X	Reset Instruction
MEMORY CYCLE:	-55				
	25				
	+100				
P. I. AM	-55				
COUNTUP:	25				
	+100	X X X	X X	X X	P. C. Fail
STACK	-55				
POINTER:	25				
	+100	X X X	X X X	X X	Stack Fail
REGISLRA	-55				
ARRAY:	25				
	+100				
ALU:	-55				
	25				
	+100	X X	X		
ROUTER	-55				
ROUTEROUT:	25				
	+100	X X X	X X	X X	Stack Fail

Device #: 2
Date: 7/22/80

TABLE 4.0

TEST	T	Vcc @ 1MHz	Vcc @ 2.0MHz	Vcc @ 2.85MHz	Clock: 15
	E				
	N	-4.5	4.75	5.0	5.25
	P	5.5	5.0	5.25	5.5
RESET	-55				
	+25	X	X	X	
	+100	X	X	X	X
				X	X
			X	X	X
			X	X	X
			X	X	X
MEMORY CYCLE:	-55				Reset Instruction
	25				
	100				
PROGRAM COUNTER:	-55				
	25	X	X	X	
	100	X	X	X	X
			X	X	X
			X	X	X
			X	X	X
STACK POINTER:	-55				
	25	X	X	X	
	100	X	X	X	X
			X	X	X
			X	X	X
REGISTER ARRAY:	-55				
	25				
	100				
ALU:	-55				
	25				
	100				
PROCESSOR INTERRUPT:	-55				
	25	X	X	X	
	100	X	X	X	X
			X	X	X
			X	X	X
			X	X	X
			XRTG = 36		

Device #:
Date: 7/22/84

Table 4.1

T	E	Vcc @ 1MHz	Vcc @ 2.0MHz	Vcc @ 2.85MHz	Comments
TEST	H	4.5 4.75 5.0 5.25 5.5	4.5 4.75 5.0 5.25 5.5	4.5 4.75 5.0 5.25 5.5	
RESET	-55				
	25				
	100				
MEMORY CYCLE:	-55				
	25				
	100				
PROGRAM	-55				
COUNTER:	25				
	100	X			P.C. Increment
STACK	-55				
POLINTER:	25				
	100	X			SP 1 byte write
REGISTER:	-55				
ARRAY:	25				
	100				
ALU:	-55				
	25				
	100				
PROCESSOR:	-55				
INTERRUPT:	25				
	100	X			SP 1 byte write

Rev 1.1
Date: 7/2/03

Table 4.2

TEST	V _E	V _{CC} @ 1MHz	V _{CC} @ 2.0MHz	V _{CC} @ 2.85MHz	CURRENT, S
	X	4.54 .5 5.0 5.25 5.5		4.54 .75 5.0 5.25 5.5	
RESET	-55				
	25				
	100				
MEMORY CYCLE:	-55				
	25				
	100				
PROGRAM COUNTER:	-55				
	25				
	100	X			P.C. Increment
STACK POINTER:	-55				
	25				
	100	X			SP 1 byte write
REGISTER ARRAY:	-55				
	25				
	100				
ALU:	-55				
	25				
	100				
PROCESSOR INTERRUPT:	-55				
	25				
	100				

Device #: 74227
Date: 1/22/74

Table 4.3

TEST	E	Vcc @ 1MHz	Vcc @ 2.0MHz	Vcc @ 2.85MHz	COMMENTS
N	I	4.5 4.75 5.0 5.25 5.5	4.5 4.75 5.0 5.25 5.5	4.5 4.75 5.0 5.25 5.5	
RESET	-55				
	25				
	100				
MEMORY CYCLE:	-55				
	25				
	100				
PROGRAM COUNTER:	-55				
	25				
	100	X			P.C. Increment
STACK POINTER:	-55				
	25				
	100	X			SP Lbyte Write
REGISLER ARRAY:	-55				
	25				
	100				
ALU:	-55				
	25				
	100				
PROCESSOR INTERRUPT:	-55				Extended Div Time
	25				
	100	X			SP Lbyte write

Device #: 7
Date: 7/12/80

Table 4.4

	T ₁ : 55	V _{CC} = 1V _{1/2}	V _{CC} < 2.0V _{1/2}	V _{CC} > 2.85V _{1/2}	Circuit Type
RESET:	11	4.54755052555	4.54755052555	4.54755052555	
RESET:	-55				Processor Read (no write)
	25				
	100	X			
MEMORY CYCLE:	-55				
	25				
	100				
PROGRAM COUNTER:	-55				
	25				
	100	X X	X	X	P.C. Increment
STACK POINTER:	-55				
	25	X X	X	X	Stack write
	100				
REGISTER ARRAY:	-55				
	25				
	100	X			XRTG = 167
ALU:	-55				
	25				
	100	X X	X	X	XRTG = 80
PROCESSOR INTERFAC:	-55				
	25				
	100	X X	X	X	XRTG = 76

[$\frac{1}{2} \text{V}_1 + \frac{1}{2}$]

[$\frac{1}{2} \text{V}_1 - \frac{1}{2}$]

Table 4.5

4.0 DEVICE EVALUATION

4.1 The data base used in evaluating the MC68000 was quite extensive. It involved three mask set iterations, devices with very noticeable process changes in addition to samples from one second source vendor (Hitachi).

The preliminary evaluation of the MC68000 was performed using the R9M mask set XC68000 device. This mask set of devices was the first set released by the vendor for user evaluation. It was not a fully functional device and therefore was shortly replaced with the T6E mask set. The R9M mask set was not evaluated using the characterization program due to the functional anomalies that were present.

The following mask set devices were evaluated using the existing characterization program.

- o T6E (10 pcs)
- o CCl - 8 MHZ (10 pcs)(early)
- o CCl - 10 MHZ (5 pcs)
- o CCl - 8 MHZ (5 pcs)(late)
- o T6E - Hitachi (6 pcs)

4.2 T6E DEVICE EVALUATION

The T6E mask set devices were tested prior to completion of the instruction decode test and AC/DC performance test. Therefore early analysis of the device was performed using the Logic Block element test (LBET) software only. Week codes for these devices were 8013 and 8019.

Shown in Table 4.0-4.5 are the functional failures for the T6E devices. The 10 samples were tested with one device indicating no functionality at +25°C. This device was deleted from the remaining tests. The remaining 9 pcs of the XC68000 (T6E) were all functional at 25°C and -55°C TCASE. Problems with 6 of the devices occurred between 90°C and 100°C (TCASE) most notably with Vcc = 4.5 volts and FREQ = 1.0 MHZ. The nature of the failure centered on small geometry devices that were either leaking or failing to keep the internal bus precharged at slow frequencies and high temperature. When the device is operated at a slow frequency 1.0 - 3.0 MHZ and at an elevated temperature (<70°C) it is believed that the nodes were not maintaining (bleeding-off) the precharged level. This resulted in the address being lost prior to being latched into the output buffer logic. This anomaly was seen in the Program Counter Test, Stack Pointer Test and (on some devices), the Reset Test.

The software was modified to perform the functional tests at 2.0 MHZ and 2.88 MHZ in addition to the 1.0 MHZ test. The data in Table 4.0 - 4.5 indicates that functionality improved with increasing frequency due to the fact that the dynamic like nodes have less time to bleed-off prior to being latched into the output buffer. This problem was to be corrected on later devices and prompted an evaluation of the CCl (8 MHZ) MC68000 mask set. Motorola,

however, changed the minimum operating frequency to 2.0 MHZ, and finally 3.0 MHZ in order to allow for the faster 8, and 10 MHZ drivers being developed

4.3 CCI (8 MHZ) DEVICE EVALUATION

4.3.1 Functional Testing

The first evaluation of the CCI mask set MC68000 was performed on 10 devices. The devices were week coded 8105.

The devices were initially screened across the mil-temp range of -55°C to +125°C (TCASE). The functional performance of the devices at the +125°C was degraded significantly from the +110°C (TCASE) performance. This resulted in the loss of a majority of the functional dependent AC-DC performance data. In evaluating the cause of the device failures it was discovered that at the elevated case temperature of +125°C, the θ_{jc} of the device (the temperature difference between junction temperature and case temperature) was approximately 10-15°C/watt. At the case temperature of 125°C, the junction temperature of a device dissipating 750 mw would be in excess of 135°C. At the date of manufacture the vendor was varying his process in order to optimize his yield and it is doubtful that the process would support functionality at this elevated temperature. The data taken at +110°C (TCASE) indicated acceptable device performance therefore functional testing was performed across a temp-range of -55°C to +110°C (TCASE).

Shown in Table 5.0-5.2 is a summary of the functional test results obtained during device testing. Due to the lengthy test time (approximately 25 min) required to test each device, the LBET portion of the functional test was bypassed. One device was found non-functional at room-temperature testing after delivery and was therefore deleted from the remaining temperature test runs.

At the -55°C (TCASE) test functional failures were noted on devices #1, #8. Device #8 exhibited high Vcc (5.5 volts) fails on select tests. The failure mechanism was found to be the status register in that during the op-code execution of CMP D5, D3, and Ext D3 (Byte) the EXTEND bit in the status register was being set. Device #1 exhibited similar failures at different Vcc levels. When tested at 25°C (TCASE) device #1 exhibited similar failures to those that were noted at the -55°C temp. test. All other devices were fully functional. The final temp. test was performed at +110°C (TCASE). Functional failures were noted on devices #7, #9. Device #7 would not process out of RESET vector Ø (power-on RESET) for any functional tests. Device #9 exhibited low Vcc (4.5 volt) fails on select tests. The failure mechanism centered on the inability of AS and DS to function properly during processor READ/WRITE operations. While this lot of devices showed significant improvement in functionality over previous T6E devices, IBM pursued testing of more mature CCL MASK product at 10 MHZ and a re-test of 8 MHZ devices to obtain full functionality at the mil temperature extremes.

INSTRUCTION DECODE FAILURE SUMMARY MC68000-LC1
(FAILURES BY DEVICE NUMBER)

SAMPLE LOT : 9 PCS
WTC CODE : B103

7-1(b)1(c), (e)

Table 5.1

Table 5.2

4.3.2 DC Parametric Tests

The minimum and maximum data values obtained across the tested temperature range are shown in Table 5.3. It was noted that one device exhibited a slightly lower VOL (2.35 volts) than desired on the Enable output. It was later learned that the enable output would be redesigned. Power dissipation was found to be 1.1 watts worse case ($V_{CC} = 5.5$ volts @ -55°C TCASE). This was within the vendors specification of 1.2 watts max. All remaining DC parameters were within the vendors specification.

4.3.3 FMAX Testing

FMAX testing indicated all devices to be operating at an FMAX of approximately 7.1 to 7.7 MHZ. The maximum frequency of operation occurs at the -55°C TCASE temperature. The 8 MHZ commercial temperature devices being tested were adequate to meet 6 MHZ military temperature operations. Therefore, the 6 MHZ commercial specifications for frequency and performance were used as pass/fail criteria for the devices in a military temperature environment.

4.3.4 AC Performance Testing

All devices were tested across the temp range of -55°C to $+110^{\circ}\text{C}$ TCASE. Shown in Table 5.4 - 5.5 are the min-max summary for all measured delays. All devices met the vendors 0°C - 70°C specification for a 6 MHZ device. It was noted during testing that the clock pulse width high delay (tch) seemed to track with the frequency of the device. Through experimentation and later correlation it was found that the frequency of the device could be determined (± 0.5 MHZ) by the following equation.

$$\text{FMAX} = 1/[2(\text{Tch}) + \text{trise} + \text{tfall}]$$

Where: trise + tfall = 6ns

Using this method of determining FMAX it was found that worse case FMAX was:

$$\begin{aligned}\text{FMAX} &= 1/[2(61)\text{ns} + 6\text{ns}] \\ &= 1/128 \text{ us} \\ &= 7.8 \text{ MHZ}\end{aligned}$$

This clearly indicated the 8 MHZ 0°C - 70°C devices could meet an FMAX of 6.0 MHZ across the temperature range of -55° to $+110^{\circ}\text{C}$ (TCASE).

4.3.5 MC68000L8 Test Summary

Overall the AC, DC and FMAX performance was found to be acceptable when compared to a 6 MHZ device specification. However, functionally the devices exhibited some unusual anomalies at the lower (-55°C) test temp. It should be noted that the devices which exhibited the cold-temperature failures were the devices having the highest FMAX. This tends to point out a parameter of the process (threshold, or ion implantation) that results in increased performance but does not support functionality at the -55°C TCASE temperature.

Table 5.3

Table 5.4

Table 5.5

It may also indicate a race condition or design problem with the device that precludes 1-2 MHZ testing on the faster devices. At the higher test temp. (+100°C) the functional failures seem to be frequency related and supports the position that the lower frequency limit of 2 MHZ must be changed to a minimum of 3 MHZ, based on data obtained.

4.4 MC68000L10 DEVICE TESTING

Device testing was performed on 5 pcs of the MC68000L10 devices. Week codes for these devices were 8116 and 8119. These devices were loaned out by the vendor for characterization purposes only and were off-the-shelf, 0°C - 70°C, 10 MHZ devices.

4.4.1 Functional testing

Functional tests results for the five devices tested are shown in Table 6.0 - 6.2. One device (#2) indicated functional failures at -55°C and +25°C TCASE temperature. All remaining devices were found to be functional. Generally, the failures were found to be related to low Vcc (4.5 volts), low frequency (2.0 MHZ). The failure mechanism was failure to process out of Power-on reset and loss of address during RD/write operations. When tested at +110°C TCASE device #2 and #5 indicated functional failures. Device #5 failures occurred at Vcc = 4.5 volts with Freq = 2.0 MHZ only. At the frequency of 2.85 MHZ device #5 was functional. Device #2 exhibited across the board failures at Vcc = 4.5 volts.

4.4.2 DC Testing

DC parametric testing was performed across the temperature range -55°C to +110°C TCASE. Shown in Table 6.3 is the summarized D.C. parametric data. All devices tested within the vendors specification. It was noted that the two devices (#2, #5) exhibited higher supply current values (Icc) than the remaining 3 devices. This was especially evident on device #2 which exhibited an Icc (171 MA) 5% ~ 10% higher than the other devices (<165 MA). It was later shown that a screen of ICC <165 MA or a functional test at 3.0 MHZ at 110°C would eliminate any potential functional fail devices.

4.4.3 FMAX Testing

All devices passed at the maximum tested FMAX of 8.33 MHZ across the temperature range of -55°C to +110°C TCASE. Calculated FMAX (see sec. 4.3.4) indicates all devices operating with FMAX = 9.2 MHZ worst case (Tc = +110°C).

4.4.4 AC Performance Testing

All 10 MHZ, 0 to 70°C commercial devices tested within the vendors' 8 MHZ specification in full mil operation, Table 6.4 shows performance measurements obtained during device testing.

Table 6.0

Table 6.1

Table 6.3

Best Award

Country	Population (1951)	1951	1955	1959	1963	1967	1971	1975	1979
Algeria	3,200,000	1,545	1,625	1,685	1,745	1,805	1,865	1,925	1,985
Angola	3,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Argentina	35,000,000	1,545	1,625	1,685	1,745	1,805	1,865	1,925	1,985
Australia	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Austria	4,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Azerbaijan	2,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Bahrain	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Bangladesh	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Barbados	200,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Bolivia	3,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Bosnia and Herzegovina	3,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Bulgaria	7,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Burma	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Cambodia	4,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Cameroon	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Canada	25,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Chad	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Chile	5,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
China	550,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Colombia	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Congo	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Croatia	4,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Cuba	6,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Cyprus	500,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Czechoslovakia	12,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Dahomey	2,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Djibouti	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Egypt	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
El Salvador	3,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Equatorial Guinea	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Eritrea	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Estonia	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Eswatini	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Finland	4,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
France	40,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Germany	40,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Greece	7,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Haiti	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Honduras	2,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Iceland	200,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Iraq	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Ireland	3,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Italy	40,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Jamaica	2,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Japan	80,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Kazakhstan	15,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Kenya	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Khazakstan	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Liberia	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Lithuania	3,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Madagascar	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Maldives	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Mali	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Mauritania	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Mauritius	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Mexico	60,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Moldova	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Mongolia	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Namibia	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Nepal	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Nicaragua	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Niger	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Nigeria	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Norway	4,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Oman	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Pakistan	100,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Panama	2,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Paraguay	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Peru	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Philippines	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Poland	30,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Portugal	4,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Romania	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Russia	150,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Rwanda	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Saint Lucia	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Saint Vincent and the Grenadines	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Samoa	100,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Saudi Arabia	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Senegal	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Serbia	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Singapore	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Slovenia	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Somalia	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Sri Lanka	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Sudan	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Taiwan	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Tajikistan	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Togo	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Tunisia	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Uganda	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Ukraine	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Uzbekistan	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Venezuela	10,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200
Yemen	1,000,000	1,200	1,200	1,200	1,200	1,200	1,200	1,200	1,200

Table 6.2

Table 6.4

4.4.5 MC68000L10 Summary

The DC, AC and FMAX data obtained on the MC68000L10 devices indicates that the devices performed extremely well across the Mil-temp range when compared to the vendors 8 MHZ 0-70°C specification. The functional failures on device #5 would not have been noted if the minimum FMAX specification was 3 MHZ. The functional problems noted with device #2 are attributed to the vendors process and can be detected with a 4.5 volt functional screen across temp. The graph shown in Figure 4.0 (ICC vs TEMP) clearly illustrates that the processing parameters of devices #2 and #5 are somewhat different from the remaining three devices. All five parts were hand-screened 8 MHZ devices for 0 to 70°C operations. It is quite obvious from the test data that the vendors process had improved significantly during the time between early 8 MHZ and these 10 MHZ device evaluations and consequently the most recent 8 MHZ should show a much improved performance.

4.5 MC68000L8 (Later Vintage) Device Testing

Based upon the data taken on the MC68000L10 devices, 5 pcs of the most recent vintage MC68000L8 were loaned by the vendor for evaluation.

4.5.1 Functional Testing

Functional testing of the most recent 8 MHZ devices indicates similar results as were obtained during 10 MHZ device testing. Shown in Table 7.0 - 7.2 is a summary of the functional test results. One device (#3) was non-functional at the -55°C test temperature. The failure mode centered on loss of address during process of RD/WRITE cycles and failure to process out of reset vector Ø (Power-on Reset) at low Vcc (4.5v). All devices were functional at +25°C. Devices #3 and #1 exhibited functional failures at the +110°C test temperature. Device #1 exhibited low Vcc/Low Freq (4.5 volts/2.0 MHZ) failures. These failures were not detected as the frequency increased (2.85 MHZ). Device #3 continued to exhibit low Vcc (4.5 volts) failures. The failure mode was similar to those noted at the -55°C test temperature.

4.5.2 D.C. Parametric Testing

All devices tested within the vendors 8 MHZ 0°-70°C specification. Shown in Table 7.3 are the D.C. test results obtained for all devices tested. Worst case supply current was measured to be 217.8 MA at Vcc = 5.5 volts @ -55°C TCASE. This translates into 1.2 watts maximum power dissipation.

4.5.3 FMAX Testing

Maximum frequency of operation for all devices tested was measured to be 7.1 MHZ (MAX). Based upon clock pulse width high calculations, the slowest device across the tested temperature was calculated to have an FMAX = 7.9 MHZ worst case.

ICC VS TEMPERATURE FOR MC68000OL10

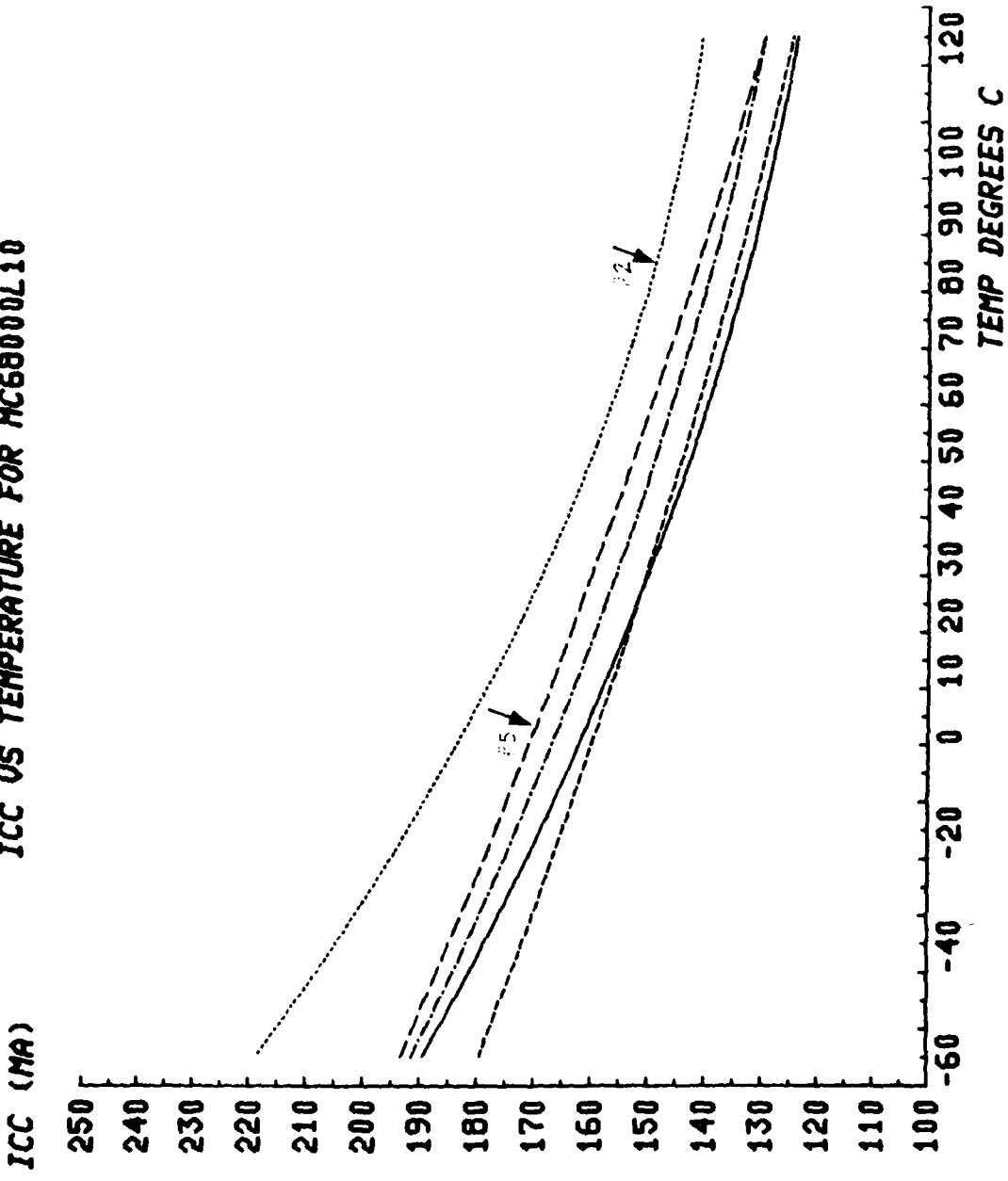


Figure 4.0

REPORT FILE INSTRUCTION DECODE FAILURE SUMMARY (MONITOR-C1
FAILURE), BY DATE: MARCH 14

Available Copy

Table 7.0

Table 7.1

Table 7.2

Table 7.3

ANSWER: The cost of building a house is \$10,000.

TEST	NAME	CONDITIONS	SPEC.	TEST DATA				N	COMMENTS
				T MIN	T MAX	V MIN	V MAX		
CLK TO CKS LOW (EDGE) [EDGE]	[EDGE]		1.25	1	-	3	1	3	1
CLK TO CKS LOW (THROUGH) [EDGE]	[EDGE]		1	-	1	4	1	4	1
DATA TO CKS LOW(SET) [THROUGH]	[THROUGH]		1.25	1	-	1	0	1	0
DATA TO CKS LOW(SET) [EDGE]	[EDGE]		1.25	1	-	1	0	1	0
DATA TO CKS LOW(SET) [SOURCE]	[SOURCE]		1.25	1	-	1	0	1	0
DATA TO CKS HIGH(SET) [THROUGH]	[THROUGH]		1.25	1	-	1	0	1	0
DATA TO CKS HIGH(SET) [EDGE]	[EDGE]		1.25	1	-	1	0	1	0
VMA TO CKS LOW (SET) [SOURCE]	[SOURCE]		1.25	1	-	1	0	1	0
VMA TO CKS LOW (THROUGH) [SOURCE]	[SOURCE]		1.25	1	-	1	0	1	0
VMA TO CKS LOW (THROUGH) [EDGE]	[EDGE]		1.25	1	-	1	0	1	0
VMA TO CKS LOW (THROUGH) [THROUGH]	[THROUGH]		1.25	1	-	1	0	1	0
VMA TO CKS LOW (THROUGH) [SOURCE]	[SOURCE]		1.25	1	-	1	0	1	0
VMA TO CKS LOW (THROUGH) [EDGE]	[EDGE]		1.25	1	-	1	0	1	0
VMA TO CKS LOW (THROUGH) [THROUGH]	[THROUGH]		1.25	1	-	1	0	1	0
CKS WIDTH LOW [EDGE]	[EDGE]		1.25	1.250	1.25	1.25	1.25	1.25	1
CKS WIDTH HIGH [TOP]	[TOP]		1.25	1.250	1.39	1.48	1.59	1.61	1
CKS HIGH TO IC VALID [TCLEAV]	[TCLEAV]		1	-	1	80	1.35	1.45	1.65
CKS HIGH TO AS LOW [TCHSLLX]	[TCHSLLX]		1	0	1	-	1.28	1.39	1.49
CKS HIGH TO AS LOW [TCHSLLN]	[TCHSLLN]		1	-	1	20	1.37	1.47	1.59
CKS HIGH TO DS LOW [TCHSLLX]	[TCHSLLX]		1	0	1	-	1.23	1.36	1.46
CKS HIGH TO DS LOW [TCHSLLN]	[TCHSLLN]		1	-	1	20	1.33	1.42	1.56
CKS LOW TO AS HIGH [TCLSSH]	[TCLSSH]		1	-	1	80	1.37	1.46	1.63
CKS LOW TO DS HIGH [TCLSSH]	[TCLSSH]		1	-	1	80	1.34	1.53	1.74
CKS H TO R-W-H [TCRHRX]	[TCRHRX]		1	0	1	-	1.23	1.29	1.34
CKS H TO R-W-H [TCRHRX]	[TCRHRX]		1	-	1	20	1.14	1.18	1.22
CKS HIGH TO R-W LOW [TCRHR]	[TCRHR]		1	-	1	80	1.13	1.25	1.28
CKS L TO BOOT VALID [TCLEBG]	[TCLEBG]		1	-	1	80	1.33	1.45	1.57
CKS L TO ADDRESS VALID [TCLEAV]	[TCLEAV]		1	-	1	80	1.48	1.58	1.71
CKS HIGH TO DG LOW [TCLEGL]	[TCLEGL]		1	-	1	80	1.14	1.20	1.30
CKS HIGH TO DG HIGH [TCLEGH]	[TCLEGH]		1	-	1	80	1.18	1.23	1.31
CKS LOW TO VMA LOW [TCLVLM]	[TCLVLM]		1	-	1	80	1.24	1.33	1.42
CKS HIGH TO VMA HIGH [TCVMM]	[TCVMM]		1	-	1	-	1.15	1.22	1.31
CKS LOW TO E LOW [TCLEFL]	[TCLEFL]		1	-	1	-	1.16	1.29	1.39
CKS LOW TO E HIGH [TCLEHM]	[TCLEHM]		1	-	1	-	1.18	1.24	1.34
CKS H TO ADDRESS [TCHAZK] VROUT +0.65V	[TCHAZK]	VROUT +0.65V	1	-	1	100	68	69	79
CKS H TO ADDRESS INVALID [TCHAZK] " "	[TCHAZK]	" "	1	0	1	-	1.65	1.66	1.77
CKS HIGH TO AS LOW [TCHEZ]	[TCHEZ]	VROUT +0.65V	1	-	1	100	48	51	56
CKS HIGH TO R-W-TIME [TCRHZ]	[TCRHZ]	" "	1	-	1	100	31	35	41
CKS HIGH TO DATA TIME [TCHAZK]	[TCHAZK]	VROUT +0.65V	1	-	1	100	57	71	101

Table 7.4

4.5.4 AC Performance

All devices tested within the vendors 0° - 70° C 6 MHZ specification. Shown in Table 7.4 are the summarized results of the data obtained during device testing.

4.5.5 MC68000L8 (Latest Vintage) Summary

It is obvious that the performance of this set of 8 MHZ devices has improved significantly from the performance of the earlier 8 MHZ devices. Shown graphically in Figures 5.0-5.1 are two trends that illustrate the performance of the later vintage 8 MHZ devices. It is obvious that at the time of manufacture the vendor was making process changes to optimize yield and performance. This resulted in somewhat different NMOS trends in the earlier devices (L8). The later vintage (L8X) device trends are nearly those of the L10 devices as evidenced by the graphs of Figures 5.0-5.1. The later vintage MC68000L8 improved functionality and performance as a direct result of the vendors matured and stabilized process.

4.6 HD68000 DEVICE TESTING

Device Testing was performed on 6 pcs of Hitachi's HD68000. Hitachi is manufacturing the device under a Mask Exchange Agreement with Motorola and are manufacturing the device using the T6E mask set. Devices were marked as HD68000 with a LD3 lot code identifier.

4.6.1 Functional Testing

Shown in Table 8.0 - 8.2 is the functional test summary for the HD68000 devices. Device testing at -55° C (TCASE) indicated functional failures on 3 devices (#2, #5, #6). These failures were very similar to the failures noted on late T6E/early C1 Mask Set device MC68000's with the faster devices exhibiting high Vcc (5.5 volt) fails at the -55° C test temp. The failure mechanism was the loss of address and improper conditions on AS, DS during processor RD/WRITE operations. Device #2 exhibited gross functional failures at the $+25^{\circ}$ C test temperature. The failure mechanism was the loss of address during processor RD/WRITE operations. All devices were functional at the $+110^{\circ}$ C (TCASE) test temperature.

4.6.2 D.C. Parametric Testing

All device parameters were within the vendors 0° - 70° C specification with the exception of supply current (Icc). Shown in Table 8.3 is the data summary obtained during device testing. Icc was measured to be 209 MA typically ($+25^{\circ}$ C). This was approximately 25% higher than typical Icc measured on the MC68000 devices. This resulted in a 1.7 watt part worst case (Vcc = 5.5 Volts, @ -55° C) and exceeded the vendors original specification of 1.2 watts maximum.

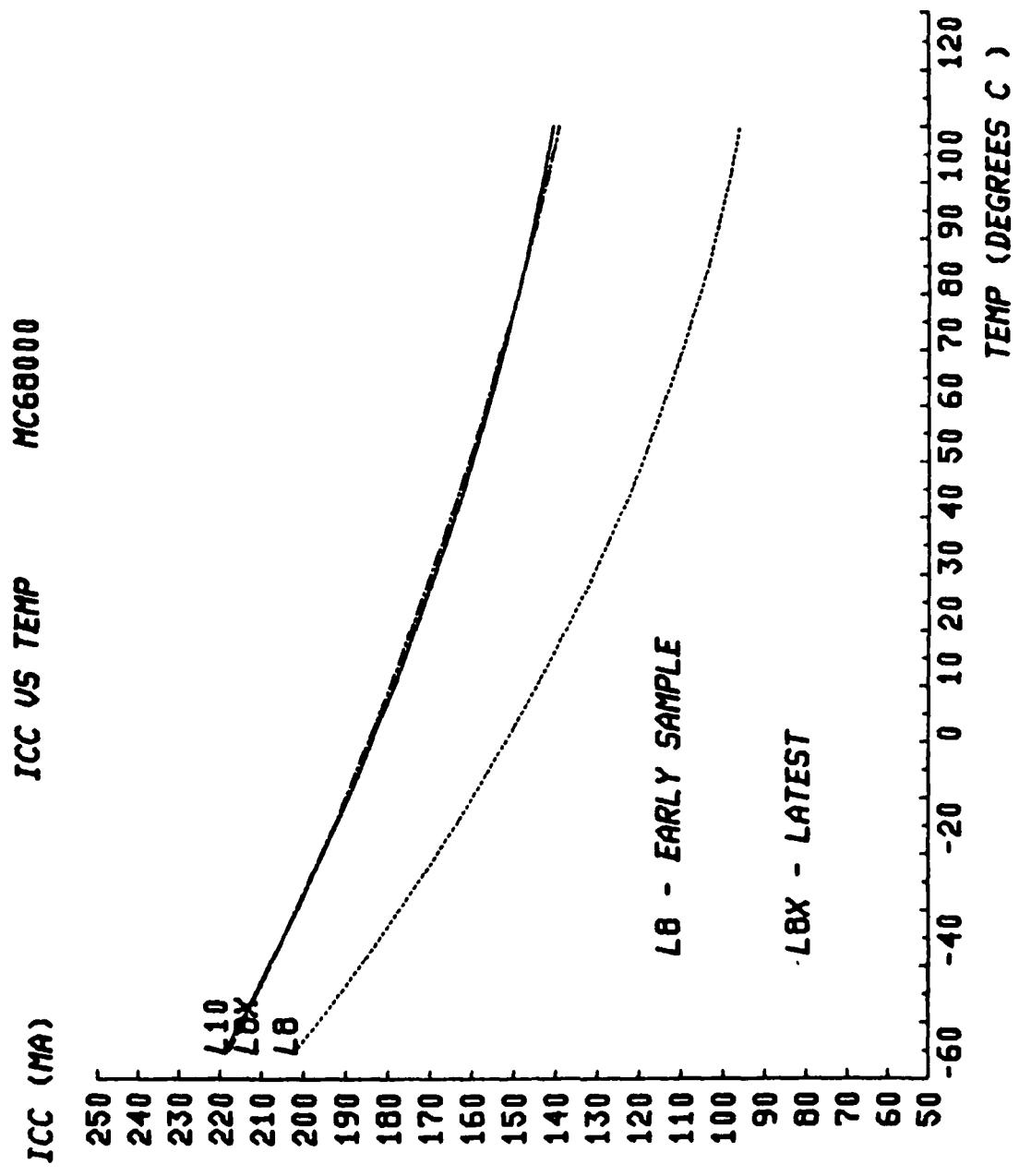


Figure 5.0

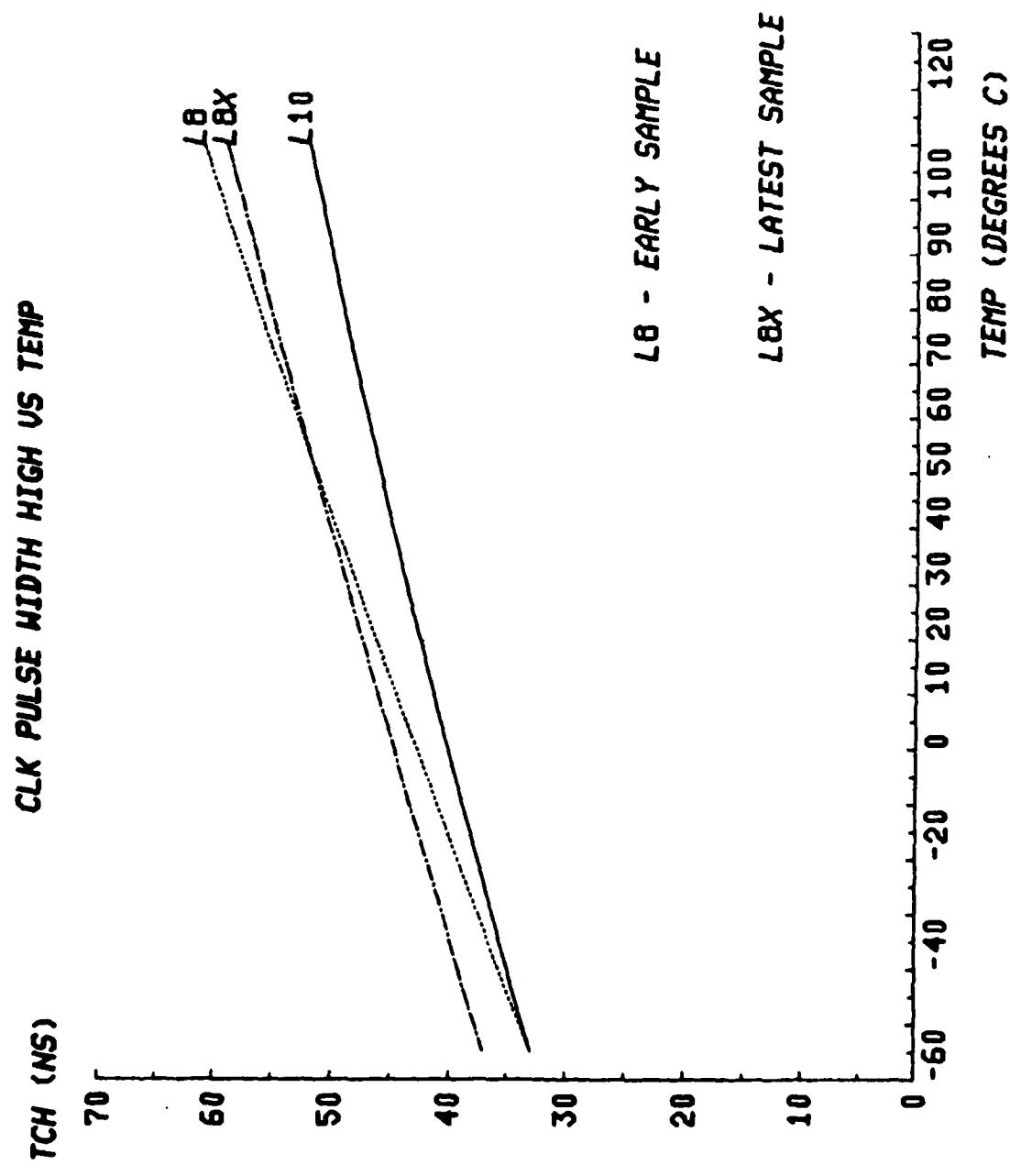


Figure 5.1

THE JOURNAL OF CLIMATE

THE JOURNAL OF CLIMATE

	FREQ MHz	FIELD MHz	FREQ MHz	FIELD MHz	CHARGE(S)
VCC	0 - 500	0 - 1100	0 - 500	0 - 1100	NO POSITION
12.0001cycles	12.0001cycles	12.0001cycles	12.0001cycles	12.0001cycles	POSITION NOTED
AT +1100					
SAU INST. TEST	4.00	1	1.0	2	1
	5.00	1	1.2	2	1
	5.50	1	1.2	2	1
	6.00	1	1.2	2	1
	6.50	1	1.4	2	1
	7.00	1	1.6	2	1
	7.50	1	1.6	2	1
	8.00	1	1.7	2	1
	8.50	1	1.7	2	1
	9.00	1	1.7	2	1
	9.50	1	1.7	2	1
	10.00	1	1.7	2	1
	10.50	1	1.7	2	1
	11.00	1	1.7	2	1
	11.50	1	1.7	2	1
	12.00	1	1.7	2	1
1388.0001INST. TEST	4.00	1	2	2	1
	5.00	1	2	2	1
	5.50	1	2	2	1
	6.00	1	2	2	1
	6.50	1	2	2	1
	7.00	1	2	2	1
	7.50	1	2	2	1
	8.00	1	2	2	1
	8.50	1	2	2	1
	9.00	1	2	2	1
	9.50	1	2	2	1
	10.00	1	2	2	1
	10.50	1	2	2	1
	11.00	1	2	2	1
	11.50	1	2	2	1
	12.00	1	2	2	1
M001.0001INST. TEST	4.00	1	1.7	2	1
	5.00	1	1.7	2	1
	5.50	1	1.7	2	1
	6.00	1	1.7	2	1
	6.50	1	1.7	2	1
	7.00	1	1.7	2	1
	7.50	1	1.7	2	1
	8.00	1	1.7	2	1
	8.50	1	1.7	2	1
	9.00	1	1.7	2	1
	9.50	1	1.7	2	1
	10.00	1	1.7	2	1
	10.50	1	1.7	2	1
	11.00	1	1.7	2	1
	11.50	1	1.7	2	1
	12.00	1	1.7	2	1
M002.0001INST. TEST	4.00	1	1.7	2	1
	5.00	1	1.7	2	1
	5.50	1	1.7	2	1
	6.00	1	1.7	2	1
	6.50	1	1.7	2	1
	7.00	1	1.7	2	1
	7.50	1	1.7	2	1
	8.00	1	1.7	2	1
	8.50	1	1.7	2	1
	9.00	1	1.7	2	1
	9.50	1	1.7	2	1
	10.00	1	1.7	2	1
	10.50	1	1.7	2	1
	11.00	1	1.7	2	1
	11.50	1	1.7	2	1
	12.00	1	1.7	2	1

Table 6

Table 8.1 Fail Test Summary (Cont.)

Table 8.2

Table 8.3

Table 8.4

4.6.3 Maximum Frequency of Operation (FMAX) testing

All devices passed the maximum tested FMAX of 8.33 MHZ at the temperature range of -55°C to $+110^{\circ}\text{C}$ (TCASE). Calculated using pulse width high, the FMAX was found to be approximately 13.8 MHZ worst case ($+110^{\circ}\text{C}$), however more samples need to be tested to guarantee this method of calculation holds true with the second vendor's process.

4.6.4 AC Testing

All device tested to within the vendors specification for a 6 MHz device shown in Table 8.4 are the AC performance results obtained during testing.

4.6.5 HD68000 Test Summary

The HD68000 device exhibited an unusually high FMAX (13.8 MHZ worst case). This is directly related to the vendors process. This is further illustrated by the supply current (Icc) data which resulted in an unusually high power dissipation. Having noted these two process parameters the functional performance was as expected. The fastest parts exhibiting the low temp (-55°C), High Vcc (5.5 volt) failures. However, it should be noted that not all the devices exhibited failures at the low temperature and that in general the devices have a higher than anticipated maximum frequency of operation. It can be expected as the vendor homes in on the corners of his process that the device failures noted during functional testing will go away resulting in a much improved MIL-temp device. In addition, the second source vendor's will be receiving next generation masks (vintage CC1) for processing. This mask set allows more margining due to critical path enhancemets.

5.0 CONCLUSION

The evaluation of the MC68000 microprocessor was a complex and time consuming task. It involved the evaluation of many different mask set devices and devices with varying performance characteristics. However, the data presented within this report clearly shows that the device from its infant stage of development (R9M MASK SET) to the present day device has matured into one of the most technologically advanced 16-bit microprocessors available. Its performance across the MIL-temp range clearly indicates its applicability to a military environment. The vendors commitment to develop and provide this device for use within a Hi-Rel market combined with the general acceptance of the device by the design community should serve to provide a valuable tool to the electronic industry.

The existance of 5 potential sources through mask exchange with Motorola will provide a highly competitive and reliable part to military users. Of the five vendors, Motorola, Hitachi, Mostek and Rockwell have samples, while Signetics plans availability in 1982.

Motorola also plans enhancements to the performance of the MC68000 up to 16 MHZ in 1982. By 1Q82, a 12 MHZ device should be available, which by past experience should yield a 10 MHZ mil-temp device.

The performance growth and large compendium of peripheral circuits planned make this processor not only an excellent present design choice, but one that will offer future growth in all military applications.

APPENDIX A

EXG

NOP
MOVE AAAA, D₁
MOVE 5555, D₇
MOVE FF00, A₁
MOVE OOFF, A₆
MOVE D₁, (A₇)
MOVE D₇, (A₇)
MOVE A₁, (A₇)
MOVE A₆, (A₇)
EXG D₁, D₇
MOVE D₁, (A₇)
MOVE D₇, (A₇)
EXG A₁, A₆
MOVE A₁, (A₇)
MOVE A₆, (A₇)
EXG D₇, A₁
MOVE D₇, (A₇)
MOVE A₁, (A₇)
EXG A₆, D₁
MOVE D₁, (A₇)
MOVE A₆, (A₇)
NOP
STOP

LEA

NOP

MOVE 0000, A₀
MOVE 0000, A₁
MOVE 0000, A₂
MOVE 0000, A₃
MOVE 0000, A₄
MOVE 0000, A₅
MOVE 0000, A₆
MOVE A₀, (A₇)
MOVE A₁, (A₇)
MOVE A₂, (A₇)
MOVE A₃, (A₇)
MOVE A₄, (A₇)
MOVE A₅, (A₇)
MOVE A₆, (A₇)
LEA xxx.W, A₀
LEA xxx.W, A₁
LEA xxx.W, A₂
LEA xxx.W, A₃
LEA xxx.W, A₄
LEA xxx.W, A₅
LEA xxx.W, A₆
MOVE A₀, (A₇)
MOVE A₁, (A₇)
MOVE A₂, (A₇)
MOVE A₃, (A₇)
MOVE A₄, (A₇)
MOVE A₅, (A₇)
MOVE A₆, (A₇)
NOP
STOP

LINK

NOP
MOVE 1000, A₁
NOP
LINK A₁, 0100
NOP
NOP
UNLINK A₁
NOP
STOP

PEA

NOP
MOVE 00001200, A₄
PEA A₄
NOP
STOP

MOVE

NOP		MOVE	$D_0, (A_7) + L. WORD$
MOVE	5555, D_0		$(PC+DISP), D_1$
	AAAA, D_7		$(PC+DISP+INDEX), D_1$
	$D_0, (A_7)$	NOP	
	$D_7, (A_7)$	STOP	
	AAAA, D_2		
	5555, D_6		
	FOFO, A_1		
	OFOF, A_6		
	$D_2, (A_7)$		
	$D_6, (A_7)$		
	$A_1, (A_7)$		
	$A_6, (A_7)$		
	AAAAAAAA, D_3		
	55555555, D_5		
	FOFOFOFO, A_2		
	OFOFOFOF, A_5		
	$D_3, (A_7)$		
	$D_5, (A_7)$		
	$A_2, (A_7)$		
	$A_5, (A_7)$		
	A_5, A_2		
	D_5, D_3		
	$A_2, (A_7)$		
	$D_3, (A_7)$		
	0000 OFOF, D_0		
	0050, D_1		
	$D_0, (A_7) L. WORD$		
	$D_0, (A_7) + D L. WORD$		
	$D_0, (A_7) + INDEX + D L. WORD$		
	$D_0, (A_7) - L. WORD$		

MOVEM

NOP		MOVE	$A_5, (A_7)$
MOVE	1200, A_6	MOVE	1300, A_6
	$D_0, (A_7)$	MOVE	REG LIST, (A_6)
	$D_1, (A_7)$	MOVE	1300, A_6
	$D_2, (A_7)$	MOVE	REG LIST (A_6)
	$D_3, (A_7)$	NOP	
	$D_4, (A_7)$	STOP	
	$D_5, (A_7)$		
	$D_6, (A_7)$		
	$D_7, (A_7)$		
	$A_0, (A_7)$		
	$A_1, (A_7)$		
	$A_2, (A_7)$		
	$A_3, (A_7)$		
	$A_4, (A_7)$		
	$A_5, (A_7)$		
	1250, A_6		
MOVEM	(A_6), REG LIST		
MOVE	$D_0, (A_7)$		
	$D_1, (A_7)$		
	$D_2, (A_7)$		
	$D_3, (A_7)$		
	$D_4, (A_7)$		
	$D_5, (A_7)$		
	$D_6, (A_7)$		
	$D_7, (A_7)$		
	$A_0, (A_7)$		
	$A_1, (A_7)$		
	$A_2, (A_7)$		
	$A_3, (A_7)$		
	$A_4, (A_7)$		

MOVEP

NOP
MOVE A000, A₀
MOVEP 55FFAAFF, D₀
MOVE D₀, (A₇)
MOVEP D₁
MOVE D₁, (A₇)
MOVE A001, A₀
MOVEP FF55FFAA, D₂
MOVE D₂, (A₇)
MOVEP D₃
MOVE D₃, (A₇)
MOVEP D₃, (A₀)
MOVEP D₂, (A₀)
MOVE A000, A₀
MOVEP D₁, (A₀)
MOVEP D₀, (A₀)
NOP
STOP

MOVEQ

NOP
MOVE 0000, D₁
MOVE 0000, D₃
MOVE 0000, D₆
MOVE D₁, (A₇)
MOVE D₃, (A₇)
MOVE D₆, (A₇)
MOVEQ 55, D₁
MOVEQ 0A, D₃
MOVEQ OF, D₆
MOVE D₁, (A₇)
MOVE D₃, (A₇)
MOVE D₆, (A₇)
NOP
STOP

MOVE A

NOP
MOVE 0000, A₀
MOVE 0000, A₃
MOVE 0000, A₆
MOVE A₀, (A₇)
MOVE A₃, (A₇)
MOVE A₆, (A₇)
MOVEA 5555AAAA, A₀
MOVE A₀, (A₇)
MOVEA A₀, A₃
MOVE A₃, (A₇)
MOVEA A₀, A₆
MOVE A₆, (A₇)
NOP
STOP

SWAP

NOP		SWAP	D ₆
MOVEQ	00, D ₀	MOVE	D ₇
	00, D ₁		D ₀ , (A ₇)
	00, D ₂		D ₁ , (A ₇)
	00, D ₃		D ₂ , (A ₇)
	00, D ₄		D ₃ , (A ₇)
	00, D ₅		D ₄ , (A ₇)
	00, D ₆		D ₅ , (A ₇)
	00, D ₇		D ₆ , (A ₇)
MOVE	D ₀ , (A ₇)	NOP	D ₇ , (A ₇)
	D ₁ , (A ₇)	STOP	
	D ₂ , (A ₇)		
	D ₃ , (A ₇)		
	D ₄ , (A ₇)		
	D ₅ , (A ₇)		
	D ₆ , (A ₇)		
	D ₇ , (A ₇)		
MOVEQ	0A, D ₀		
	55, D ₁		
	0A, D ₂		
	55, D ₃		
	0A, D ₄		
	55, D ₅		
	0A, D ₆		
	55, D ₇		
SWAP	D ₀		
	D ₁		
	D ₂		
	D ₃		
	D ₄		
	D ₅		

ADD

NOP		ADDQ	5, A ₀
MOVE	5555, D ₁	MOVE	SR, (A ₇)
MOVE	AAAA, D ₃	MOVE	A ₀ , (A ₇)
MOVE	0FOF, A ₁	ADDQ	5, (A ₆)
MOVE	FOFO, A ₃	MOVE	SR, (A ₇)
MOVE	D ₁ , (A ₇)	MOVE	(A ₆), (A ₇)
MOVE	D ₃ , (A ₇)	NOP	
MOVE	A ₁ , (A ₇)	STOP	
MOVE	A ₃ , (A ₇)		
ADD	AAAA, D ₁		
MOVE	SR, (A ₇)		
MOVE	D ₁ , (A ₇)		
ADD	5555, D ₃		
MOVE	SR, (A ₇)		
MOVE	D ₃ , (A ₇)		
MOVE	FOFO, D ₁		
ADD	D ₁ , D ₀		
MOVE	SR, (A ₇)		
MOVE	D ₁ , (A ₇)		
MOVE	00FO, D ₃		
MOVE	0050, D ₁		
ADD	D ₃ , D ₁		
MOVE	SR, (A ₇)		
MOVE	D ₁ , (A ₇)		
MOVE	0000, D ₀		
MOVE	5555, A ₀		
MOVE	1300, A ₆		
MOVE	AAAA, (A ₆)		
ADDQ	5, D ₀		
MOVE	SR, (A ₇)		
MOVE	D ₀ , (A ₇)		

ADDX

NOP
MOVE 0000, D₂
MOVE 5555, D₄
MOVE 12FE, A₂
MOVE 1300, A₆
MOVE 0505, A₅
MOVE D₂, (A₇)
MOVE D₄, (A₇)
MOVE A₂, (A₇)
MOVE A₄, (A₇)
MOVE 2700, SR
ADDX D₂, D₄
MOVE SR, (A₇)
MOVE D₄, (A₂)
MOVE 5555, D₂
MOVE 0000, D₄
MOVE 2710, SR
ADDX D₄, D₂
MOVE SR, (A₇)
MOVE D₂, (A₇)
NOP
STOP

CLR

NOP
MOVE FFFF, D₀
MOVE FFFF, D₁
MOVE FFFF, D₂
MOVE FFFF, D₃
MOVE D₀, (A₇)
MOVE D₁, (A₇)
MOVE D₂, (A₇)
MOVE D₃, (A₇)
CLR D₀
MOVE SR, (A₇)
CLR D₁
MOVE SR, (A₇)
CLR D₂
MOVE SR, (A₇)
CLR D₃
MOVE SR, (A₇)
MOVE D₀, (A₇)
MOVE D₁, (A₇)
MOVE D₂, (A₇)
MOVE D₃, (A₇)
MOVE 1374, A₆
MOVE 1350, A₅
MOVE 1324, A₄
CLR (A₆)
CLR (A₅)
CLR (A₄)
NOP
STOP

CMP

NOP		CMPI	5555, (A ₆)
MOVE	00AA, D ₃	MOVE	SR, (A ₇)
MOVE	0055, D ₅	MOVE	(A ₆), (A ₇)
MOVE	1350, A ₆	MOVE	1300, A ₆
MOVE	D ₃ , (A ₇)	MOVE	1376, A ₄
MOVE	D ₅ , (55)	MOVE	00AA, (A ₆)
CMP	D ₅ , D ₃	MOVE	AAAA, (A ₄)
MOVE	SR, (A ₇)	MOVE	2700, SR
MOVE	D ₃ , (A ₇)	CMPM	(A ₆), (A ₄)
MOVE	00AA, D ₃	MOVE	SR, (A ₇)
MOVE	0055, D ₅	NOP	
CMP	D ₃ , D ₅	STOP	
MOVE	SR, (A ₇)		
MOVE	D ₅ , (A ₇)		
MOVE	0055, D ₃		
MOVE	0055, D ₅		
CMP	D ₅ , D ₃		
MOVE	SR, (A ₇)		
MOVE	D ₃ , (A ₇)		
MOVE	00AA, (A ₆)		
MOVE	00AA, D ₅		
CMP	(A ₆), D ₅		
MOVE	SR, (A ₇)		
MOVE	D ₅ , (A ₇)		
MOVE	AAAA, D ₀		
MOVE	1300, A ₆		
MOVE	AAAA, (A ₆)		
MOVE	2700, SR		
CMPI	AAAA, D ₀		
MOVE	SR, (A ₇)		
MOVE	D ₀ , (A ₇)		

EXT

MOVE	0004, D ₀
MOVE	0084, D ₃
MOVE	D ₀ , (A ₇)
MOVE	D ₃ , (A ₇)
EXT	D ₀
MOVE	SR, (A ₇)
MOVE	D ₀ , (A ₇)
EXT	D ₃
MOVE	SR, (A ₇)
MOVE	D ₀ , (A ₇)
MOVE	7FFF, D ₀
MOVE	800F, D ₃
MOVE	D ₀ , (A ₇)
MOVE	D ₃ , (A ₇)
EXT	D ₀
MOVE	SR, (A ₇)
MOVE	D ₀ , (A ₇)
EXT	D ₃
MOVE	SR, (A ₂)
MOVE	D ₃ , (A ₂)
NOP	
STOP	

MULS

NOP
MOVE 5555, D₀
MOVE 0002, D₁
MOVE 2700, SR
MOVE D₀, (A₇)
MOVE D₁, (A₇)
MULS D₁, D₀
MOVE SR, (A₇)
MOVE D₀, (A₇)
MOVE OOFF, D₀
MOVE 0000, D₁
MOVE 2700, SR
MULS D₁, D₀
MOVE SR, (A₂)
MOVE D₀, (A₇)
MOVE 5555, D₀
MOVE FFFC, D₁
MULS D₁, D₂
MOVE SR, (A₇)
MOVE D₀, (A₇)
NOP
STOP

NEG

NOP		MOVE	D ₅ , (A ₇)
MOVE	0000, D ₀	MOVE	0OFF, D ₀
MOVE	0000, D ₃	MOVE	00AA, D ₃
MOVE	0000, D ₅	MOVE	00000055, D ₅
MOVE	D ₀ , (A ₇)	MOVE	2710, SR
MOVE	D ₃ , (A ₇)	NEG	D ₀
MOVE	D ₅ , (A ₇)	MOVE	SR, (A ₇)
MOVE	5555, D ₃	MOVE	D ₀ , (A ₇)
MOVE	AAAA, D ₅	MOVE	2710, SR
NEG	D ₀	NEGX	D ₅
MOVE	SR, (A ₇)	MOVE	SR, (A ₇)
MOVE	D ₀ , (A ₇)	MOVE	D ₅ , (A ₇)
NEG	D ₃	MOVE	2710, SR
MOVE	SR, (A ₇)	NEGX	(A ₆)
MOVE	D ₃ , (A ₇)	MOVE	SR, (A ₇)
NEG	D ₅	MOVE	(A ₆), (A ₇)
MOVE	SR, (A ₇)	MOVE	2700, SR
MOVE	D ₅ , (A ₇)	NEGX	(A ₆)
NOP		MOVE	SR, (A ₇)
MOVE	1300, A ₆	MOVE	(A ₆), (A ₇)
MOVE	5555, (A ₆)	NOP	
MOVE	0001, D ₀	STOP	
MOVE	00AA, D ₃		
MOVE	55555555, D ₅		
MOVE	2700, SR		
NEGX	D ₀		
MOVE	SR, (A ₇)		
MOVE	D ₃ , (A ₇)		
MOVE	2700, SR		
NEGX	D ₅		
MOVE	SR, (A ₇)		

SUBI

NOP		MOVE	SR, (A ₇)
MOVE	AAAA, D ₀	MOVE	A ₀ , (A ₇)
MOVE	5555, D ₂	SUBQ	7, D ₂
MOVE	FFFF, D ₄	MOVE	SR, (A ₇)
MOVE	D ₀ , (A ₇)	MOVE	D ₂ , (A ₇)
MOVE	D ₂ , (A ₇)	MOVE	5555, D ₁
MOVE	D ₄ , (A ₇)	MOVE	AAAA, D ₀
SUBI	5555, D ₀	MOVE	2700, SR
MOVE	SR, (A ₇)	SUBX	D ₁ , D ₀
MOVE	D ₀ , (A ₇)	MOVE	SR, (A ₇)
SUBI	AAAA, D ₂	MOVE	D ₀ , (A ₇)
MOVE	SR, (A ₇)	MOVE	5555, D ₁
MOVE	D ₀ , (A ₇)	MOVE	AAAA, D ₀
SUBI	0FFF, D ₄	MOVE	2710, SR
MOVE	SR, (A ₇)	SUBX	D ₁ , D ₀
MOVE	D ₄ , (A ₇)	MOVE	SR, (A ₇)
MOVE	AAAAAAA, D ₀	MOVE	D ₀ , (A ₇)
MOVE	55555555, D ₂	NOP	
SUBI	55555555, D ₀	STOP	
MOVE	SR, (A ₇)		
MOVE	D ₀ , (A ₇)		
SUBI	AAAAAAA, D ₂		
MOVE	SR, (A ₇)		
MOVE	D ₂ , (A ₇)		
MOVE	AAAA, D ₀		
MOVE	5555, A ₀		
MOVE	0000, D ₂		
SUBQ	5, D ₀		
MOVE	SR, (A ₇)		
MOVE	D ₀ , (A ₇)		
SUBQ	5, A ₀		

AND

NOP

MOVE AAAA, D₀
MOVE 5555, D₁
MOVE FFFF, A₀
MOVE 0000, D₂
MOVE 1300, A₆
MOVE FOFO, (A₆)
AND D₀, D₁
MOVE SR, (A₇)
MOVE D₀, (A₇)
MOVE D₁, (A₇)
AND (A₆), D₂
MOVE SR, (A₇)
MOVE D₂, (A₇)
MOVE 5555, D₀
MOVE AAAA, A₀
MOVE 1300, A₆
MOVE FOFO, (A₆)
ANDI 0050, D₀
MOVE SR, (A₇)
MOVE D₀, (A₇)
ANDI 0050, (A₆)
MOVE SR, (A₇)
NOP
STOP

OR

NOP
MOVE 1300, A₆
MOVE F0F0, (A₆)
MOVE AAAA, D₀
MOVE 2700, SR
OR D₀, (A₆)
MOVE SR, (A₇)
MOVE D₀, (A₇)
MOVE 5500, D₀
MOVE 0F00, D₁
OR D₀, D₁
MOVE SR, (A₇)
MOVE D₁, (A₇)
MOVE OF0F, D₀
MOVE 0505, D₁
MOVE A0A0, (A₆)
ORI 0500, D₀
MOVE SR, (A₇)
MOVE D₀, (A₇)
ORI OF, D₁
MOVE SR, (A₇)
MOVE D₁, (A₇)
ORI FO, (A₆)
MOVE SR, (A₇)
NOP
STOP

NOT

NOP
MOVE F0F0, D₀
MOVE 1300, A₆
MOVE A0A0, (A₆)
NOT D₀
MOVE SR, (A₇)
MOVE D₀, (A₇)
NOT (A₆)
MOVE SR, (A₇)
NOP
MOVE 0001, D₀
MOVE 0008, D₁
MOVE 8000, D₂
ASL 7, D₀
MOVE SR, (A₇)
MOVE D₀, (A₇)
MOVE 0001, D₀
ASI D₁, 0
MOVE SR, (A₇)
MOVE D₀, (A₇)
ASR D₂, 7
MOVE SR, (A₇)
MOVE D₂, (A₇)
MOVE 8000, D₂
ASR D₂, D₁
MOVE SR, (A₇)
MOVE D₂, (A₇)
NOP
MOVE 0001, D₂
MOVE 8000, D₄
MOVE 0008, D₆

NOT (CONT)

LSL	7, D ₂	MOVE	2710, SR
MOVE	SR, (A ₇)	MOVE	8000, D ₁
MOVE	D ₂ , (A ₇)	ROR	D ₂ , D ₁
MOVE	0001, D ₂	MOVE	SR, (A ₇)
LSL	D ₆ , D ₂	MOVE	D ₁ , (A ₇)
MOVE	SR, (A ₇)	MOVE	0000, D ₀
MOVE	D ₂ , (A ₇)	MOVE	2710, SR
LSR	D ₄ , 7	ROXL	7, D ₀
MOVE	SR, (A ₇)	MOVE	SR, (A ₇)
MOVE	D ₄ , (A ₇)	MOVE	D ₀ , (A ₇)
MOVE	8000, D ₄	MOVE	0000, D ₀
LSR	D ₄ , D ₆	MOVE	2700, SR
MOVE	SR, (A ₇)	ROXL	D ₂ , D ₀
MOVE	D ₄ , (A ₇)	MOVE	SR, (A ₇)
NOP		MOVE	D ₀ , (A ₇)
MOVE	0001, D ₀	MOVE	0000, D ₁
MOVE	8000, D ₁	MOVE	2710, SR
MOVE	0008, D ₂	ROXR	7, D ₁
MOVE	2710, SR	MOVE	SR, (A ₇)
ROL	7, D ₀	MOVE	D ₁ , (A ₇)
MOVE	SR, (A ₇)	MOVE	0000, D ₁
MOVE	D ₀ , (A ₇)	MOVE	2700, SR
MOVE	2710, SR	ROXR	D ₂ , D ₁
MOVE	0001, D ₀	MOVE	SR, (A ₇)
ROL	D ₂ , D ₀	MOVE	D ₁ , (A ₇)
MOVE	SR, (A ₇)	NOP	
MOVE	D ₀ , (A ₇)	STOP	
MOVE	2700, SR		
ROR	7, D ₁		
MOVE	SR, (A ₇)		
MOVE	D ₁ , (A ₇)		

BTST

NOP		MOVE	SR, (A ₇)
MOVE	0880, D ₀	MOVE	D ₀ , (A ₇)
MOVE	2700, SR	BCLR	0002, D ₀
MOVE	0800, D ₁	MOVE	SR, (A ₇)
BTST	D ₀ , 0007	MOVE	D ₀ , (A ₇)
MOVE	SR, (A ₇)	MOVE	0008, D ₀
BTST	D ₀ , 0001	MOVE	0000, D ₁
MOVE	SR, (A ₇)	MOVE	0004, D ₂
BTST	D ₀ , D ₁	MOVE	2700, SR
MOVE	SR, (A ₇)	BCHG	D ₀ , D ₁
NOP		MOVE	SR, (A ₇)
MOVE	0007, D ₀	MOVE	D ₁ , (A ₇)
MOVE	0000, D ₂	BCHG	D ₂ , D ₁
MOVE	0006, D ₄	MOVE	SR, (A ₇)
MOVE	2700, SR	MOVE	D ₁ , (A ₇)
BSET	D ₄ , D ₂	BCHG	0002, D ₂
MOVE	SR, (A ₇)	MOVE	SR, (A ₇)
MOVE	D ₂ , (A ₇)	MOVE	D ₂ , (A ₇)
BSET	D ₁ , D ₂	NOP	
MOVE	SR, (A ₇)	STOP	
MOVE	D ₂ , (A ₇)		
BSET	0001, D ₂		
MOVE	SR, (A ₇)		
MOVE	D ₂ , (A ₇)		
MOVE	00F0, D ₀		
MOVE	0008, D ₁		
MOVE	0004, D ₂		
BCLR	D ₁ , D ₀		
MOVE	SR, (A ₇)		
MOVE	D ₀ , (A ₇)		
BCLR	D ₂ , D ₀		

BCD

NOP		MOVE	D ₁ , (A ₇)
MOVE	0000, D ₁	MOVE	2710, SR
MOVE	0012, D ₂	SBCD	D ₃ , D ₂
MOVE	0022, D ₃	MOVE	SR, (A ₇)
MOVE	2700, SR	MOVE	D ₂ , (A ₇)
MOVE	1300, A ₆	MOVE	1302, A ₆
MOVE	0012, (A ₆)	MOVE	1352, A ₅
MOVE	1350, A ₅	SBCD	(A ₅), (A ₆)
MOVE	0012, (A ₅)	MOVE	SR, A ₇
ABCD	D ₂ , D ₁	MOVE	0000, D ₁
MOVE	SR, (A ₇)	MOVE	FFFF, SR
MOVE	D ₁ , (A ₇)	MOVE	2700, SR
MOVE	2710, SR	NBCD	D ₂
ABCD	D ₃ , D ₂	MOVE	SR, (A ₇)
MOVE	SR, (A ₇)	MOVE	D ₂ , (A ₇)
MOVE	D ₂ , (A ₇)	MOVE	2710, (A ₇)
MOVE	2700, SR	NBCD	D ₁
MOVE	1302, A ₆	MOVE	SR, (A ₇)
MOVE	1352, A ₅	MOVE	D ₁ , (A ₇)
ABCD	(A ₅), (A ₆)	NOP	
MOVE	SR, (A ₇)	STOP	
MOVE	0000, D ₁		
MOVE	0012, D ₂		
MOVE	0022, D ₃		
MOVE	2700, SR		
MOVE	1300, A ₆		
MOVE	0012, (A ₆)		
MOVE	1350, A ₅		
MOVE	0012, (A ₅)		
SBCD	D ₂ , D ₁		
MOVE	SR, (A ₇)		

PGCNT

100E	NOP
	MOVE 000F, D ₀
	MOVE 00F0, D ₁
	MOVE 000F, D ₂
	CMP D ₁ , D ₀
	BRAcc ≠, 1050
1050	NOP
	MOVE 000F, D ₁
	CMP D ₁ , D ₀
	DBcc =, 1200
1200	NOP
	MOVE D ₂ , (A ₇)
	MOVE 0000, D ₁
	SETcc ≠, D ₂
	MOVE D ₂ , (A ₇)
	BRA 1250
1250	NOP
	BSR 1300
	NOP
	BSR 1350
1300	NOP
	MOVE 1450, A ₆
	RTS
1350	NOP
	MOVE SR, (A ₇)
	RTR
	NOP
	STOP

ADDA

NOP		MOVE	SR, (A ₇)
MOVE	00000000, A ₁	MOVE	A ₁ , (A7)
MOVE	000000F0, A ₂	NOP	
MOVE	1300, A ₆	STOP	
MOVE	0000000F, (A ₆)		
MOVE	2700, SR		
ADDA	A ₂ , A ₁		
MOVE	SR, (A ₇)		
MOVE	A ₁ , (A ₇)		
MOVE	00000AOA, A ₁		
ADDA	(A ₆), A ₁		
MOVE	SR, (A ₇)		
MOVE	A ₁ , (A ₇)		
MOVE	00000000, A ₁		
MOVE	00000FF0, A ₂		
MOVE	00000FF0, A ₃		
MOVE	2700, SR		
CMPA	A ₁ , A ₂		
MOVE	SR, (A ₇)		
MOVE	A ₂ , (A ₇)		
CMP	A ₃ , A ₂		
MOVE	SR, (A ₇)		
MOVE	A ₂ , (A ₇)		
MOVE	00000AOA, A ₁		
MOVE	00000AO0, A ₂		
MOVE	1300, A ₆		
MOVE	0000000A, (A ₆)		
SUBA	A ₂ , A ₁		
MOVE	SR, (A ₇)		
MOVE	A ₁ , (A ₇)		
SUBA	(A ₆), A ₁		

SYSTEM CONTROL

NOP			
MOVE	00000AOA, A ₁	MOVE	0010, CCR
	2700, SR		SR, (A ₇)
	USP A ₁ T	NOP	
	SR, (A ₇)	NOP	
	00G00000, A ₁	NOP	
	USP A ₁ E	MOVE	SR, (A ₇)
	SR, (A ₇)	STOP	
	A ₁ , (A ₇)		
	2700, SR		
	SR, (A ₇)		
	2701, SR		
	SR, (A ₇)		
	2702, (A ₇)		
	SR, (A ₇)		
	2704, SR		
	SR, (A ₇)		
	2708, SR		
	SR, (A ₇)		
	270A, SR		
	SR, (A ₇)		
	0000, CCR		
	SR, (A ₇)		
	0001, CCR		
	SR, (A ₇)		
	0002, CCR		
	SR, (A ₇)		
	0004, CCR		
	SR, (A ₇)		
	0008, CCR		
	SR, (A ₇)		

CHK

NOP
MOVE 1000, D₃
MOVE 0500, D₁
MOVE 2000, D₂
MOVE 2700, SR
CHK D₁, D₃
NOP
NOP
MOVE 2700, SR
NOP
CHK D₂, D₃
NOP
STOP

DIVS

NOP
MOVE AAAA, D₁
MOVE 0002, D₂
MOVE 2700, SR
DIV D₀, D₁
MOVE AAAA, D₁
MOVE FFFFFFFE, D₀
MOVE 2700, SR
DIV D₀, D₁
NOP
STOP

TAS

NOP
MOVE 1300, A₆
MOVE 0000, D₀
MOVE 00F0, D₂
MOVE 2700, SR
TAS D₀
MOVE SR, (A₇)
MOVE D₀, (A₇)
MOVE 2700, (A₇)
TAS D₂
MOVE SR, (A₇)
MOVE D₂, (A₇)
MOVE AAAA, (A₆)
MOVE 2700, SR
TAS (A₆)
MOVE SR, (A₇)
MOVE (A₆), (A₇)
MOVE 0000, D₀
MOVE F000, D₂
MOVE 2700, SR
TST D₀
MOVE SR, (A₇)
MOVE 2700, SR
TST D₂
MOVE SR, (A₇)
NOP
STOP

APPENDIX B

DEVICE NUMBER 1 AT 25 DEG. CENT.

***** MC68000 DC PARAMETRICS *****

1: ICC TEST (FREQ = 6MHZ) VCC = 5.5 VOLTS	CHAN 0 = 161.719	MA
2: VOL I A23=1,FCR (0.5V # 3.2MA)I	CHAN 1 = .169581	V
	CHAN 2 = .18	V
	CHAN 3 = .187521	V
	CHAN 4 = .187501	V
	CHAN 5 = .194281	V
	CHAN 6 = .1935	V
	CHAN 7 = .1965	V
	CHAN 8 = .196	V
	CHAN 9 = .202501	V
	CHAN 10 = .202501	V
	CHAN 11 = .211501	V
	CHAN 12 = .210501	V
	CHAN 13 = .2145	V
	CHAN 14 = .220001	V
	CHAN 15 = .223501	V
	CHAN 16 = .224501	V
	CHAN 17 = .233501	V
	CHAN 18 = .2345	V
	CHAN 19 = .239	V
	CHAN 20 = .239	V
	CHAN 21 = .242501	V
	CHAN 22 = .2375	V
	CHAN 23 = .2375	V
3: VOL I FCI (0.5V # 3.2MA)I	CHAN 24 = .169581	V
4: VOL I AS,DS,R-W (0.5V # 5.3MA)I	CHAN 25 = .285501	V
	CHAN 26 = .283301	V
	CHAN 27 = .2135	V
	CHAN 28 = .279001	V
5: VOL I DATA0 I (0.5V # 5.3 MA)I	CHAN 29 = .257501	V
6: VOL I DATA1 I (0.5V # 5.3 MA)I	CHAN 30 = .267	V
7: VOL I DATA2 I (0.5V # 5.3 MA)I	CHAN 31 = .263581	V
8: VOL I DATA3 I (0.5V # 5.3 MA)I	CHAN 32 = .2715	V
9: VOL I DATA4 I (0.5V # 5.3 MA)I	CHAN 33 = .2725	V
10: VOL I DATA5 I (0.5V # 5.3 MA)I	CHAN 34 = .2785	V
11: VOL I DATA6 I (0.5V # 5.3 MA)I	CHAN 35 = .2785	V
12: VOL I DATA7 I (0.5V # 5.3 MA)I	CHAN 36 = .282801	V
13: VOL I DATA8 I (0.5V # 5.3 MA)I	CHAN 37 = .284	V
14: VOL I DATA9 I (0.5V # 5.3 MA)I	CHAN 38 = .287801	V
15: VOL I DATA10 I (0.5V # 5.3 MA)I	CHAN 39 = .2875	V

161 VOL : DATA11 : (0.5V # 5.3 MA):	CHAN 2 = .292001	V
171 VOL : DATA12 : (0.5V # 5.3 MA):	CHAN 2 = .2895	V
181 VOL : DATA13 : (0.5V # 5.3 MA):	CHAN 2 = .299501	V
191 VOL : DATA14 : (0.5V # 5.3 MA):	CHAN 2 = .298501	V
201 VOL : DATA15 : (0.5V # 5.3 MA):	CHAN 2 = .307801	V
211 VOL : BG (0.5V # 3.2MA):	CHAN 57 = .154001	V
221 VOL : E (0.5V # 3.2MA):	CHAN 53 = .760031E-01	V
231 VOL : VMA (0.5V # 5.3 MA):	CHAN 52 = .146	V
241 VOL : FC2 (0.5V # 3.2MA):	CHAN 8 = .160501	V
251 VOL : RESET (0.5V # 5MA):	CHAN 2 = .211001	V
261 VOL : HALT (0.5V # 1.6MA):	CHAN 54 = .203	V
271 VOH : ADR,FC2%0,BG (2.4V # 400UA):	CHAN 6 = 3.35501 CHAN 8 = 3.34501 CHAN 9 = 3.36521 CHAN 10 = 3.35001 CHAN 11 = 3.36521 CHAN 12 = 3.35521 CHAN 13 = 3.38001 CHAN 14 = 3.36501 CHAN 15 = 3.39001 CHAN 16 = 3.38501 CHAN 17 = 3.39001 CHAN 18 = 3.39001 CHAN 19 = 3.39501 CHAN 20 = 3.40001 CHAN 21 = 3.42501 CHAN 22 = 3.41001 CHAN 23 = 3.42501 CHAN 24 = 3.40001 CHAN 25 = 3.40501 CHAN 26 = 3.37501 CHAN 27 = 3.38501 CHAN 28 = 3.40001 CHAN 29 = 3.44001 CHAN 30 = 3.43501 CHAN 31 = 3.45501 CHAN 57 = 3.36501	V
281 VOH : DATA0 : (2.4V # 400 UA):	CHAN 2 = 3.33001	V
291 VOH : DATA1 : (2.4V # 400 UA):	CHAN 2 = 3.33001	V
301 VOH : DATA2 : (2.4V # 400 UA):	CHAN 2 = 3.32501	V
311 VOH : DATA3 : (2.4V # 400 UA):	CHAN 2 = 3.33001	V
321 VOH : DATA4 : (2.4V # 400 UA):	CHAN 2 = 3.32501	V
331 VOH : DATA5 : (2.4V # 400 UA):	CHAN 2 = 3.32501	V
341 VOH : DATA6 : (2.4V # 400 UA):	CHAN 2 = 3.33501	V

351	VDM 1 DATA7 3 (2.4V ± 400 UA)±	CHAN 2 = 3.34581	V
361	VDM 1 DATA8 3 (2.4V ± 400 UA)±	CHAN 2 = 3.35501	V
371	VDM 1 DATA9 3 (2.4V ± 400 UA)±	CHAN 2 = 3.36001	V
381	VDM 1 DATA10 3 (2.4V ± 400 UA)±	CHAN 2 = 3.37501	V
391	VDM 1 DATA11 3 (2.4V ± 400 UA)±	CHAN 2 = 3.37501	V
401	VDM 1 DATA12 3 (2.4V ± 400 UA)±	CHAN 2 = 3.40001	V
411	VDM 1 DATA13 3 (2.4V ± 400 UA)±	CHAN 2 = 3.37501	V
421	VDM 1 DATA14 3 (2.4V ± 400 UA)±	CHAN 2 = 3.39001	V
431	VDM 1 DATA15 3 (2.4V ± 400 UA)±	CHAN 2 = 3.36501	V
441	VDM 1 AS,UDS,LDS,HR,FC1(2.4V ± 400UA)1	CHAN 7 = 3.35001 CHAN 60 = 3.37201 CHAN 61 = 3.36301 CHAN 62 = 3.39501 CHAN 63 = 3.38501	V
451	VDM 1 E,VMA (2.4V ± 400UA)±	CHAN 52 = .250001E-01 CHAN 53 = 3.35301	FAIL
461	IIM 1 ALL INPUTS (1.0UA ± 2.4 VOLTS)±	CHAN 4 = .1E-02 CHAN 5 = -.250001E-02 CHAN 32 = .200001E-02 CHAN 33 = -.15E-02 CHAN 34 = .200001E-02 CHAN 35 = -.250001E-02 CHAN 36 = -.500001E-03 CHAN 37 = .350001E-02 CHAN 38 = -.250001E-02 CHAN 39 = .300001E-02 CHAN 40 = .1E-02 CHAN 41 = -.350001E-02 CHAN 42 = .200001E-02 CHAN 43 = -.350001E-02 CHAN 44 = -.500001E-03 CHAN 45 = .200001E-02 CHAN 46 = -.350001E-02 CHAN 47 = .250001E-02 CHAN 48 = -.250001E-02 CHAN 49 = .15E-02 CHAN 50 = -.300001E-02 CHAN 51 = .15E-02 CHAN 54 = .500001E-03 CHAN 55 = -.350001E-02 CHAN 56 = .200001E-02 CHAN 58 = -.350001E-02 CHAN 59 = .200001E-02	UA
471	IIL 1 ALL INPUTS (1.0UA ± 0.4 VOLTS)±	CHAN 4 = .500001E-03 CHAN 5 = -.250001E-02 CHAN 32 = .250001E-02 CHAN 33 = -.300001E-02 CHAN 34 = .200001E-02 CHAN 35 = .500001E-03 CHAN 36 = -.450001E-02 CHAN 37 = .300001E-02	UA

CHAN 39 E = -.293201E-02 UA
CHAN 40 E = .1114E-02 UA
CHAN 41 E = -.1470021E-02 UA
CHAN 42 E = .116E-02 UA
CHAN 43 E = -.157201E-02 UA
CHAN 44 E = .317E-02 UA
CHAN 45 E = -.251201E-02 UA
CHAN 46 E = .201201E-02 UA
CHAN 47 E = -.187201E-02 UA
CHAN 48 E = .221201E-02 UA
CHAN 49 E = -.357201E-02 UA
CHAN 50 E = .371201E-02 UA
CHAN 51 E = -.311201E-02 UA
CHAN 52 E = .251201E-02 UA
CHAN 53 E = .591201E-03 UA
CHAN 54 E = -.457201E-02 UA
CHAN 55 E = .281201E-02 UA
CHAN 56 E = -.10E-02

481 10HZ : ALL OUTPUTS (7 UA @ 2.4VOLTS): CHAN 6 E = -.100201E-02 UA
CHAN 7 E = -.100201E-02 UA
CHAN 8 E = -.952201E-03 UA
CHAN 9 E = -.952201E-03 UA
CHAN 10 E = -.100201E-02 UA
CHAN 11 E = -.11E-02 UA
CHAN 12 E = -.952201E-03 UA
CHAN 13 E = -.949201E-03 UA
CHAN 14 E = -.100201E-02 UA
CHAN 15 E = -.105E-02 UA
CHAN 16 E = -.125E-02 UA
CHAN 17 E = -.949201E-03 UA
CHAN 18 E = -.949201E-03 UA
CHAN 19 E = -.100201E-02 UA
CHAN 20 E = -.105E-02 UA
CHAN 21 E = -.105E-02 UA
CHAN 22 E = -.900201E-03 UA
CHAN 23 E = -.100201E-02 UA
CHAN 24 E = -.952201E-03 UA
CHAN 25 E = -.952201E-03 UA
CHAN 26 E = -.11E-02 UA
CHAN 27 E = -.949201E-03 UA
CHAN 28 E = -.949201E-03 UA
CHAN 29 E = -.100201E-02 UA
CHAN 30 E = -.949201E-03 UA
CHAN 31 E = -.100201E-02 UA
CHAN 32 E = -.100201E-02 UA
CHAN 33 E = -.949201E-03 UA
CHAN 34 E = -.949201E-03 UA
CHAN 35 E = -.952201E-03 UA
CHAN 36 E = -.105E-02 UA
CHAN 37 E = -.952201E-03 UA
CHAN 38 E = -.105E-02 UA
CHAN 39 E = -.105E-02 UA
CHAN 40 E = -.11E-02 UA
CHAN 41 E = -.11E-02 UA
CHAN 42 E = -.952201E-03 UA
CHAN 43 E = -.105E-02 UA
CHAN 44 E = -.100201E-02 UA
CHAN 45 E = -.100201E-02 UA
CHAN 46 E = -.949201E-03 UA
CHAN 47 E = -.100201E-02 UA
CHAN 48 E = -.100201E-03 UA

CHAN 11	=	53	NS
CHAN 12	=	59	NS
CHAN 13	=	59	NS
CHAN 14	=	65	NR
CHAN 15	=	64	NS
CHAN 16	=	54	NS
CHAN 17	=	49	NS
CHAN 18	=	60	NS
CHAN 19	=	59	NS
CHAN 20	=	56	NS
CHAN 21	=	56	NS
CHAN 22	=	52	NS
CHAN 23	=	61	NS
CHAN 24	=	54	NS
CHAN 25	=	51	NS
CHAN 26	=	54	NS
CHAN 27	=	65	NS
CHAN 28	=	66	NS
CHAN 29	=	62	NS
CHAN 30	=	63	NS
CHAN 31	=	59	NS

2731CLK H TO ADDR. INVALID (VOM & VOL)=2.5V

CHAN 9	=	59	NS
CHAN 10	=	58	NS
CHAN 11	=	57	NS
CHAN 12	=	53	NS
CHAN 13	=	51	NS
CHAN 14	=	65	NS
CHAN 15	=	64	NS
CHAN 16	=	54	NS
CHAN 17	=	49	NS
CHAN 18	=	60	NS
CHAN 19	=	59	NS
CHAN 20	=	57	NS
CHAN 21	=	58	NS
CHAN 22	=	60	NS
CHAN 23	=	61	NS
CHAN 24	=	54	NS
CHAN 25	=	51	NS
CHAN 26	=	64	NS
CHAN 27	=	65	NS
CHAN 28	=	60	NS
CHAN 29	=	62	NS
CHAN 30	=	63	NS
CHAN 31	=	58	NS

2741CLK HIGH TO AS,DS T.S. (VOM = 2.5V)

CHAN 62	=	47	NS
CHAN 61	=	35	NS
CHAN 63	=	49	NS

2751CLK HIGH TO R=H T.S. (VOM=0.5V)

CHAN 62	=	22	NS
---------	---	----	----

2761CLK HIGH TO DATA T.S. ITCHAZX (100NS MAX)

CHAN 32	=	58	NS
CHAN 33	=	52	NS
CHAN 34	=	51	NS
CHAN 35	=	48	NS
CHAN 36	=	46	VS
CHAN 37	=	47	NS
CHAN 38	=	53	NS
CHAN 39	=	56	NS
CHAN 40	=	55	NS
CHAN 41	=	44	NS
CHAN 42	=	49	NS
CHAN 43	=	51	NS
CHAN 44	=	48	NS
CHAN 45	=	51	VS
CHAN 46	=	63	NS
CHAN 47	=	53	NS

CHAN 50 = -.182271E-02 UA
CHAN 51 = -.175E-02 UA
CHAN 52 = -.149281E-02 UA
CHAN 53 = -.14941E-02 UA

49: IDLZ : ALL OUTPUTS (7 UA @ 0.4 VOLTS): CHAN 5 = -.173271E-02 UA
CHAN 6 = -.952271E-03 UA
CHAN 7 = -.952271E-03 UA
CHAN 8 = -.109221E-02 UA
CHAN 10 = -.952271E-03 UA
CHAN 11 = -.122221E-02 UA
CHAN 12 = -.97221E-03 UA
CHAN 13 = -.950001E-03 UA
CHAN 14 = -.122221E-02 UA
CHAN 15 = -.125E-02 UA
CHAN 16 = -.109221E-02 UA
CHAN 17 = -.122221E-02 UA
CHAN 18 = -.122221E-02 UA
CHAN 19 = -.105E-02 UA
CHAN 20 = -.122221E-02 UA
CHAN 21 = -.952271E-03 UA
CHAN 22 = -.921001E-03 UA
CHAN 23 = -.100701E-02 UA
CHAN 24 = -.107221E-02 UA
CHAN 25 = -.952271E-03 UA
CHAN 26 = -.105E-02 UA
CHAN 27 = -.952271E-03 UA
CHAN 28 = -.952271E-03 UA
CHAN 29 = -.125E-02 UA
CHAN 30 = -.100001E-02 UA
CHAN 31 = -.122221E-02 UA
CHAN 32 = -.920271E-03 UA
CHAN 33 = -.120001E-02 UA
CHAN 34 = -.100001E-02 UA
CHAN 35 = -.920271E-03 UA
CHAN 36 = -.952271E-03 UA
CHAN 37 = -.100001E-02 UA
CHAN 38 = -.105E-02 UA
CHAN 39 = -.922271E-03 UA
CHAN 40 = -.100001E-02 UA
CHAN 41 = -.852271E-03 UA
CHAN 42 = -.940001E-03 UA
CHAN 43 = -.11E-02 UA
CHAN 44 = -.122221E-02 UA
CHAN 45 = -.952271E-03 UA
CHAN 46 = -.900001E-03 UA
CHAN 47 = -.122221E-02 UA
CHAN 57 = -.11E-02 UA
CHAN 58 = -.104001E-02 UA
CHAN 59 = -.952271E-03 UA
CHAN 60 = -.952271E-03 UA
CHAN 63 = -.122221E-02 UA

58: INPUT LOW TEST (ALL INPUTS) : V_{VCC} = 4.5 I_{IL} MAX = 1 V

511 INPUT HIGH TEST (ALL INPUTS) : V_{VCC} = 4.5 I_{IH} MIN = 1.55224 V

81:	5.5	PASS
**** INTEGER ARITHMETIC INSTRUCTIONS ****		
82: ADD,ADDD INSTRUCTION TEST	4.5	PASS
83:	5	PASS
84:	5.5	PASS
85: ADDX INST. TEST	4.5	PASS
86:	5	PASS
87:	5.5	PASS
88: CLR INST. TEST	4.5	PASS
89:	5	PASS
90:	5.5	PASS
91: CMP,CMPI,CMPM INST. TEST	4.5	PASS
92:	5	PASS
93:	5.5	PASS
94: DIV,DIVS INST. TEST	4.5	PASS
95:	5	PASS
96:	5.5	PASS
97: EXT INST. TEST	4.5	PASS
98:	5	PASS
99:	5.5	PASS
100: MULU AND MULS INST. TEST	4.5	PASS
101:	5	PASS
102:	5.5	PASS
103: NEG,NEGX INST. TEST	4.5	PASS
104:	5	PASS
105:	5.5	PASS
106: SUB,SUBI,SUBG,SUBX INST. TEST	4.5	PASS
107:	5	PASS
108:	5.5	PASS
109: TAS,TST INST. TEST	4.5	PASS
110:	5	PASS

AD-A111 491

IBM FEDERAL SYSTEMS DIV MANASSAS VA
ELECTRICAL CHARACTERIZATION OF THE 68000 MICROPROCESSOR. (U)

F30602-80-C-0119

F/G 9/2

DEC 81 J D BAILEY

RADC-TR-81-350

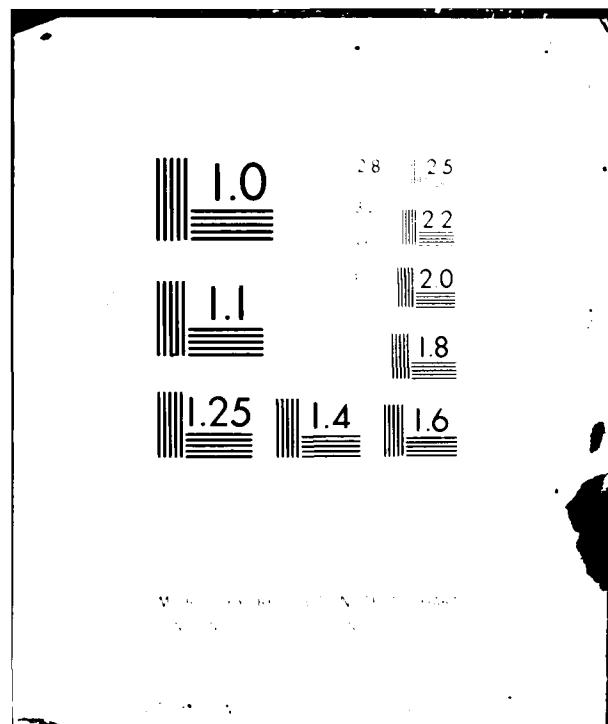
NL

UNCLASSIFIED

2 OF 2

AD-A111
491

END
DATE
FILED
103-182
DTIC



1111	5.5	PASS
**** SHIFT, ROTATE, AND LOGICAL INSTRUCTIONS ****		
1121 AND, ANDI INST. TEST	4.5	PASS
1131	5	PASS
1141	5.5	PASS
1151 OR, ORI, EOR INST. TEST	4.5	PASS
1161	5	PASS
1171	5.5	PASS
1181 NOT, SHIFT & ROTATE INST. TEST	4.5	PASS
1191	5	PASS
1201	5.5	PASS
**** BIT MANIPULATION INSTRUCTIONS ****		
1211 BIT(TST,SET,CLR,CHG) INST. TEST	4.5	PASS
1221	5	PASS
1231	5.5	PASS
**** BCD INSTRUCTIONS		
1241 BCD (ADD,SUB,NEG) INST. TEST	4.5	PASS
1251	5	PASS
1261	5.5	PASS
**** PROGRAM AND SYSTEM, CONTROL INSTRUCTIONS ****		
1271 BRANCH, JMP AND RET INST. TEST	4.5	PASS
1281	5	PASS
1291	5.5	PASS
1301 ADDA, SUBA, CMPA INST. TEST	4.5	PASS
1311	5	PASS
1321	5.5	PASS
1331 HUSP, HSR, HCCR INST. TEST	4.5	PASS
1341	5	PASS
1351	5.5	PASS
1361 TRAP, TRAPV INST. TEST	4.5	PASS
1371	5	PASS
1381	5.5	PASS
1391 MC68000 INSTRUCTION DECODE VERIFICATION @ 2.85MHz		
**** DATA MOVE INSTRUCTIONS ****		
1391 EXB INST. TEST	4.5	PASS

140:	5	PASS
141:	5.5	PASS
142: LEA INST. TEST	4.5	PASS
143:	5	PASS
144:	5.5	PASS
145: PEA INST. TEST	4.5	PASS
146:	5	PASS
147:	5.5	PASS
148: LINK,UNLINK INST. TEST	4.5	PASS
149:	5	PASS
150:	5.5	PASS
151: MOVE INST. TEST	4.5	PASS
152:	5	PASS
153:	5.5	PASS
154: MOVEM INST. TEST	4.5	PASS
155:	5	PASS
156:	5.5	PASS
157: MOVEP INST. TEST	4.5	PASS
158:	5	PASS
159:	5.5	PASS
160: MOVEA INST. TEST	4.5	PASS
161:	5	PASS
162:	5.5	PASS
163: MOVEQ INST. TEST	4.5	PASS
164:	5	PASS
165:	5.5	PASS
166: SWAP INST. TEST	4.5	PASS
167:	5	PASS
168:	5.5	PASS
**** INTEGER ARITHMETIC INSTRUCTIONS ****		
169: ADD,ADDD INSTRUCTION TEST	4.5	PASS
170:	5	PASS

171:	5.5	PASS
172: ADDX INST. TEST	4.5	PASS
173:	5	PASS
174:	5.5	PASS
175: CLR INST. TEST	4.5	PASS
176:	5	PASS
177:	5.5	PASS
178: CMP,CMPI,CMPM INST. TEST	4.5	PASS
179:	5	PASS
180:	5.5	PASS
181: DIV,DIVS INST. TEST	4.5	PASS
182:	5	PASS
183:	5.5	PASS
184: EXT INST. TEST	4.5	PASS
185:	5	PASS
186:	5.5	PASS
187: MULU AND MULS INST. TEST	4.5	PASS
188:	5	PASS
189:	5.5	PASS
190: NEG,NEGX INST. TEST	4.5	PASS
191:	5	PASS
192:	5.5	PASS
193: SUB,SUBI,SUBQ,SUBX INST. TEST	4.5	PASS
194:	5	PASS
195:	5.5	PASS
196:		
196: TAS,TST INST. TEST	4.5	PASS
197:	5	PASS
198:	5.5	PASS
**** SHIFT,ROTATE,AND LOGICAL INSTRUCTIONS ****		
199: AND,ANDI INST. TEST	4.5	PASS
200:	5	PASS

2011:	5.5	PASS
2021: OR, ORI, EUR INST. TEST	4.5	PASS
2031:	5	PASS
2041:	5.5	PASS
2051: NOT, SHIFT & ROTATE INST. TES4.5	4.5	PASS
2061:	5	PASS
2071:	5.5	PASS
**** BIT MANIPULATION INSTRUCTIONS ****		
2081: BIT(TST,SET,CLR,CMG) INST. TE84.5	4.5	PASS
2091:	5	PASS
2101:	5.5	PASS
**** BCD INSTRUCTIONS		
2111: BCD (ADD,SUB,NEG) INST. TEST 4.5	4.5	PASS
2121:	5	PASS
2131:	5.5	PASS
**** PROGRAM AND SYSTEM, CONTROL INSTRUCTIONS ****		
2141: BRANCH, JMP AND RET INST. TE84.5	4.5	PASS
2151:	5	PASS
2161:	5.5	PASS
2171: ADDA, SUBA, CMPA INST. TEST 4.5	4.5	PASS
2181:	5	PASS
2191:	5.5	PASS
2201: MUSP, MSR, MCCR INST. TEST	4.5	PASS
2211:	5	PASS
2221:	5.5	PASS
2231: TRAP, TRAPV INST. TEST	4.5	PASS
2241:	5	PASS
2251:	5.5	PASS

DEVICE NUMBER: 1 AT 25 DEG. CENT.

*** FMAX TEST ***

2261 FMAX TEST @ 4MHZ	4.5	PASS
2271	5	PASS
2281	5.5	PASS
2291 FMAX TEST @ 5.88MHZ	4.5	PASS
2301	5	PASS
2311	5.5	PASS
2321 FMAX TEST @ 7.14MHZ	4.5	PASS
2331	5	PASS
2341	5.5	PASS
2351 FMAX TEST @ 7.7MHZ	4.5	PASS
2361	5	PASS
2371	5.5	PASS
2381 FMAX TEST @ 8.3MHZ	4.5	PASS
2391	5	PASS
2401	5.5	PASS

DEVICE NUMBER: 1 AT 25 DEG. CENT.

***** MC68000 AC PERFORMANCE TESTS *****

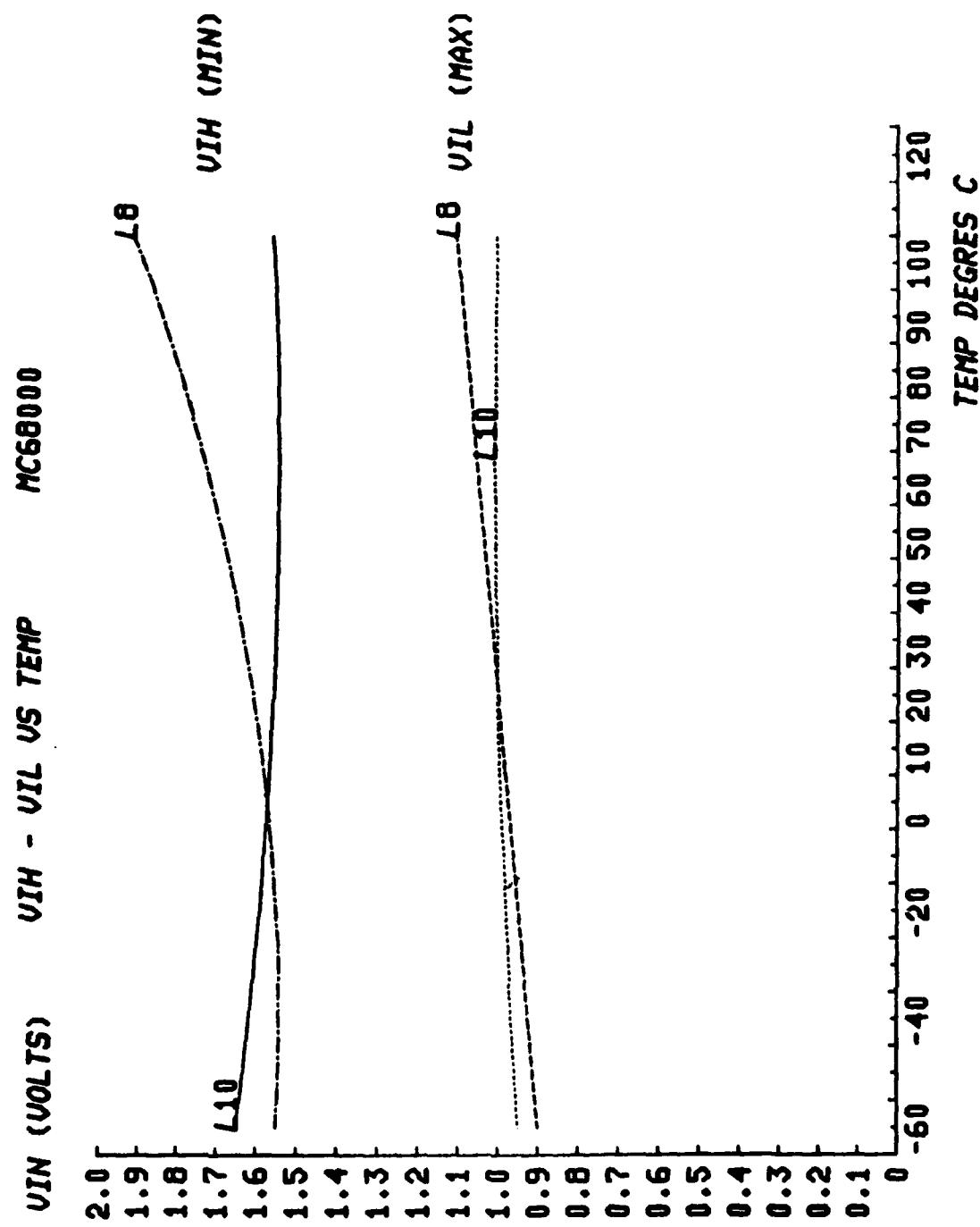
ALL SPECIFICATIONS REFLECT A 6 MHZ DEVICE

241: DIN TO CLK LOW (TSET): TDICL (25NS MIN):	CHAN 62 = 2	NS
242: DIN TO CLK LOW (THOLD): THDICL :	CHAN 62 = 0	NS
243: DTACK TO CLK LOW (TSET): TSOTCL (25NS MIN):	CHAN 62 = 0	NS
244: BR TO CLA LOW (TSET): TSBRCL :	CHAN 57 = 2	NS
245: BR TO CLK LOW (THOLD): THBRCL :	CHAN 57 = 2	NS
246: BGACK TO CLK LOW (TSET): TSBGCL :	CHAN 57 = -1	NS
247: BGACK TO CLK LOW	CHAN 57 = 0	NS
248: VPA TO CLK LOW (TSET): TSVPACL :	CHAN 52 = -5	NS
249: VPA TO CLK LOW (THULD): THVPACL :	CHAN 52 = -3	NS
250: BERR TO CLK LOW (TSET): TSBERCL :	CHAN 62 = 3	NS
251: BERR TO CLK LOW (THOLD): THBERCL :	CHAN 62 = 4	NS
252: CLK WIDTH LOW : TCL (75NS MIN):	CHAN 32 = -22 CHAN 33 = -22 CHAN 34 = -22 CHAN 35 = -22	NS
253: CLK WIDTH HIGH : TCH (75NS MIN):	CHAN 32 = 42 CHAN 33 = 41 CHAN 34 = 41 CHAN 35 = 41	NS
254: CLK HIGH TO FC VALID : TCLAV (80NS MAX):	CHAN 6 = 30 CHAN 7 = 34	NS
255: CLK HIGH TO AS LOW (MIN): TCHSLX (20NS MIN):	CHAN 63 = 33	NS
256: CLK HIGH TO AS LOW (MAX): TCHSLN (70NS MAX):	CHAN 63 = 40	NS
257: CLK HIGH TO DS LOW (MIN): TCHSLX (20NS MIN):	CHAN 68 = 31 CHAN 61 = 29	NS
258: CLK HIGH TO DS LOW (MAX): TCHSLN (70NS MAX):	CHAN 68 = 37 CHAN 61 = 34	NS
259: CLK LOW TO AS HIGH: TCLSH (80NS MAX):	CHAN 63 = 41	NS
260: CLK LOW TO DS HIGH: TCLSH (80NS MAX):	CHAN 66 = 48 CHAN 61 = 49	NS
261: CLK H TO R-W H (MAX): JCHRHW (80NS MAX):	CHAN 62 = 25	NS

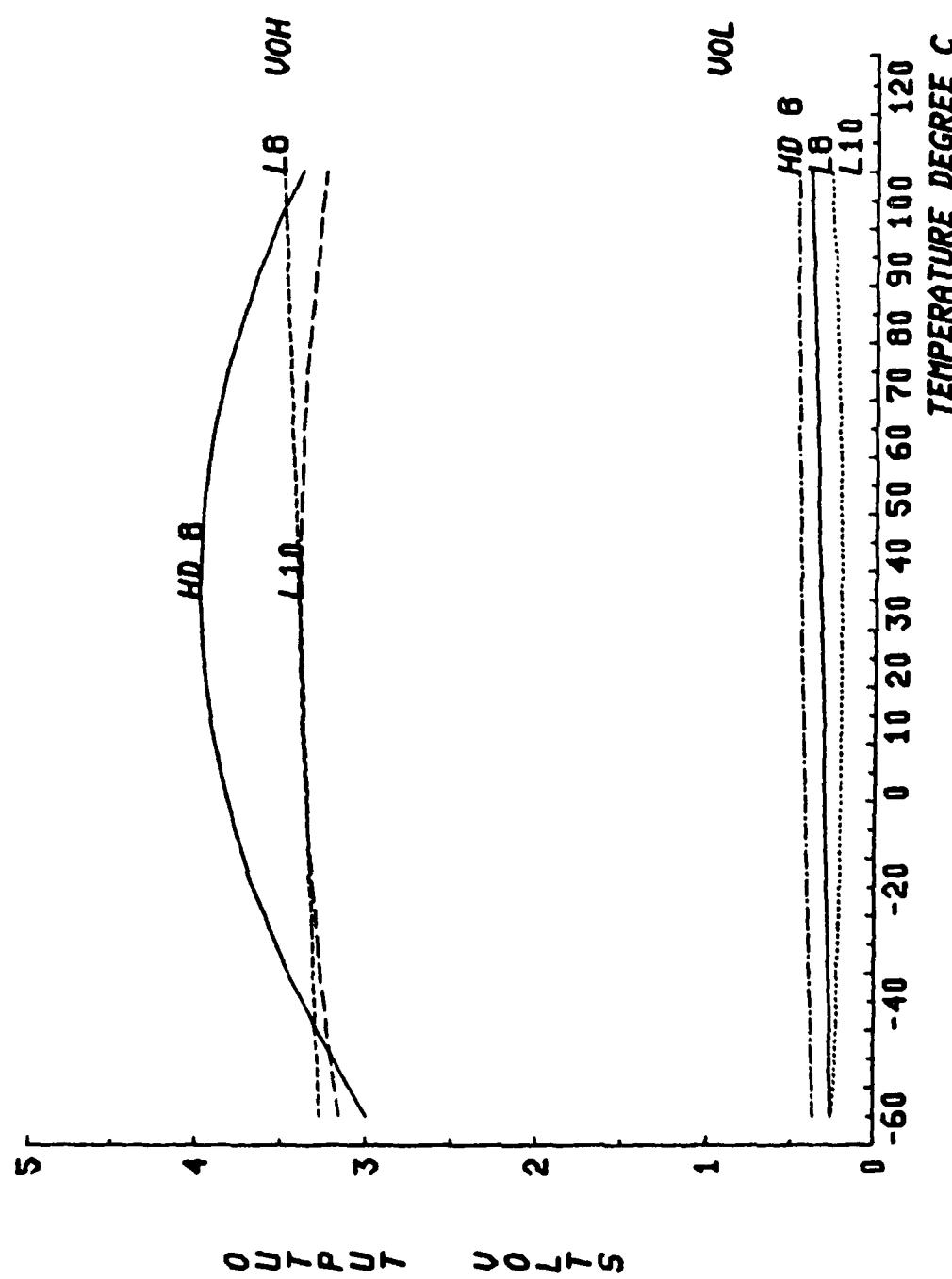
262: CLK H TO R-W H (MIN): TCHRHX (20NS MIN):	CHAN 62 = 15	NR
263: CLK HIGH TO R-W LOW: TCHRL (80NS MAX):	CHAN 62 = 19	NS
264: CLK LOW TO DOUT VALID: TCLDD (80NS MAX):	CHAN 32 = 35 CHAN 33 = 34 CHAN 34 = 36 CHAN 35 = 37 CHAN 36 = 34 CHAN 37 = 34 CHAN 38 = 33 CHAN 39 = 36 CHAN 40 = 36 CHAN 41 = 33 CHAN 42 = 36 CHAN 43 = 34 CHAN 44 = 33 CHAN 45 = 35 CHAN 46 = 0 CHAN 47 = 30	NS
265: CLK L TO ADDR. VALID: TCLKAV (80NS MAX):	CHAN 9 = 41 CHAN 10 = 38 CHAN 11 = 47 CHAN 12 = 39 CHAN 13 = 47 CHAN 14 = 49 CHAN 15 = 50 CHAN 16 = 46 CHAN 17 = 29 CHAN 18 = 49 CHAN 19 = 53 CHAN 20 = 35 CHAN 21 = 44 CHAN 22 = 32 CHAN 23 = 0 CHAN 24 = 46 CHAN 25 = 46 CHAN 26 = 45 CHAN 27 = 49 CHAN 28 = 49 CHAN 29 = 50 CHAN 30 = 45 CHAN 31 = 45	NS
266: CLK HIGH TO BG LOW : TCHGL (80NS MAX):	CHAN 57 = 19	NS
267: CLK HIGH TO BG HIGH : TCHGH (80NS MAX):	CHAN 57 = 20	NS
268: CLK LOW TO VMA LOW : TCLVML (80NS MAX):	CHAN 52 = 29	NS
269: CLK HIGH TO VMA HIGH : TCHVMM :	CHAN 52 = 22	NS
270: CLK LOW TO E LOW : TCLEL :	CHAN 53 = 25	NS
271: CLK LOW TO E HIGH : TCLEH :	CHAN 53 = 21	NS
272: CLK H TO ADDR.-FC T.R. (VOM & VOL)=0.5V	CHAN 6 = 57 CHAN 7 = 56 CHAN 8 = 58 CHAN 9 = 60 CHAN 10 = 63	NS

APPENDIX C

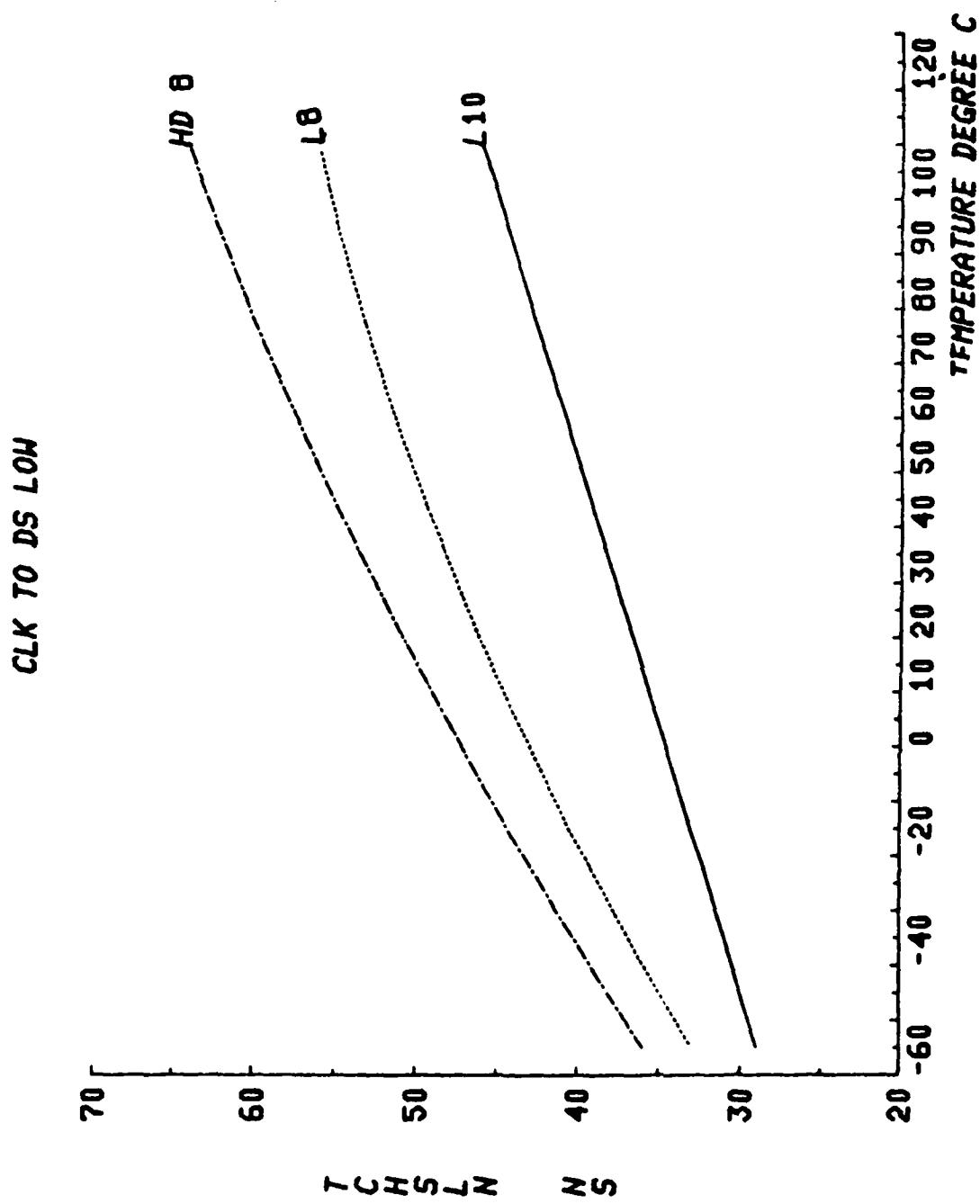
THE FOLLOWING GRAPHS ARE SELECT PARAMETERS OBTAINED FROM THE MOST RECENT MC68000L8, MC68000L10 AND HITACHI HD68000 DEVICES. THE DATA IS REPRESENTATIVE OF THE WORSE CASE DATA OBTAINED ACROSS THE TEMPERATURE RANGE OF -55^oC TO +110^oC T_{CASE}.



VOL - VOH VS TEMPERATURE

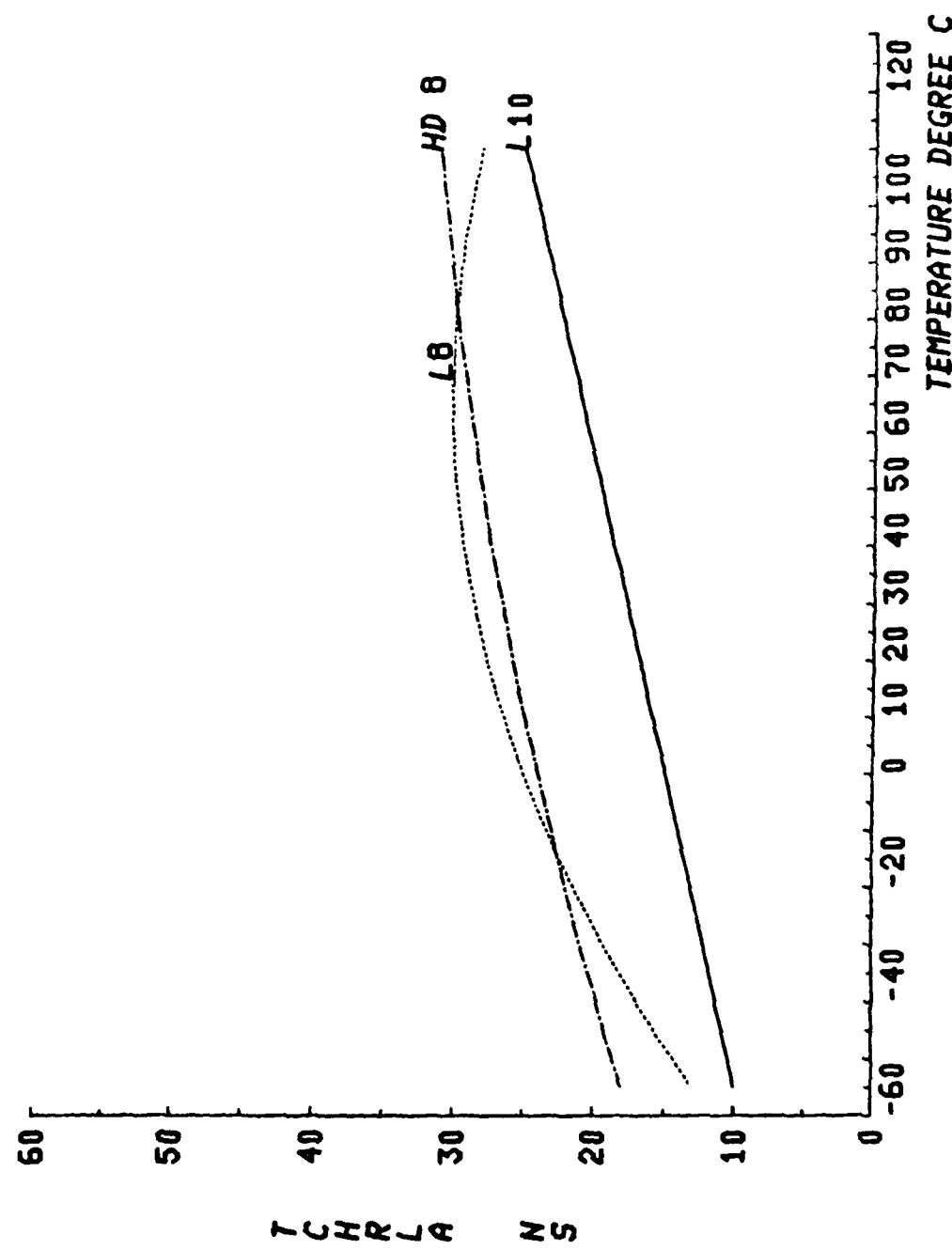


C-3

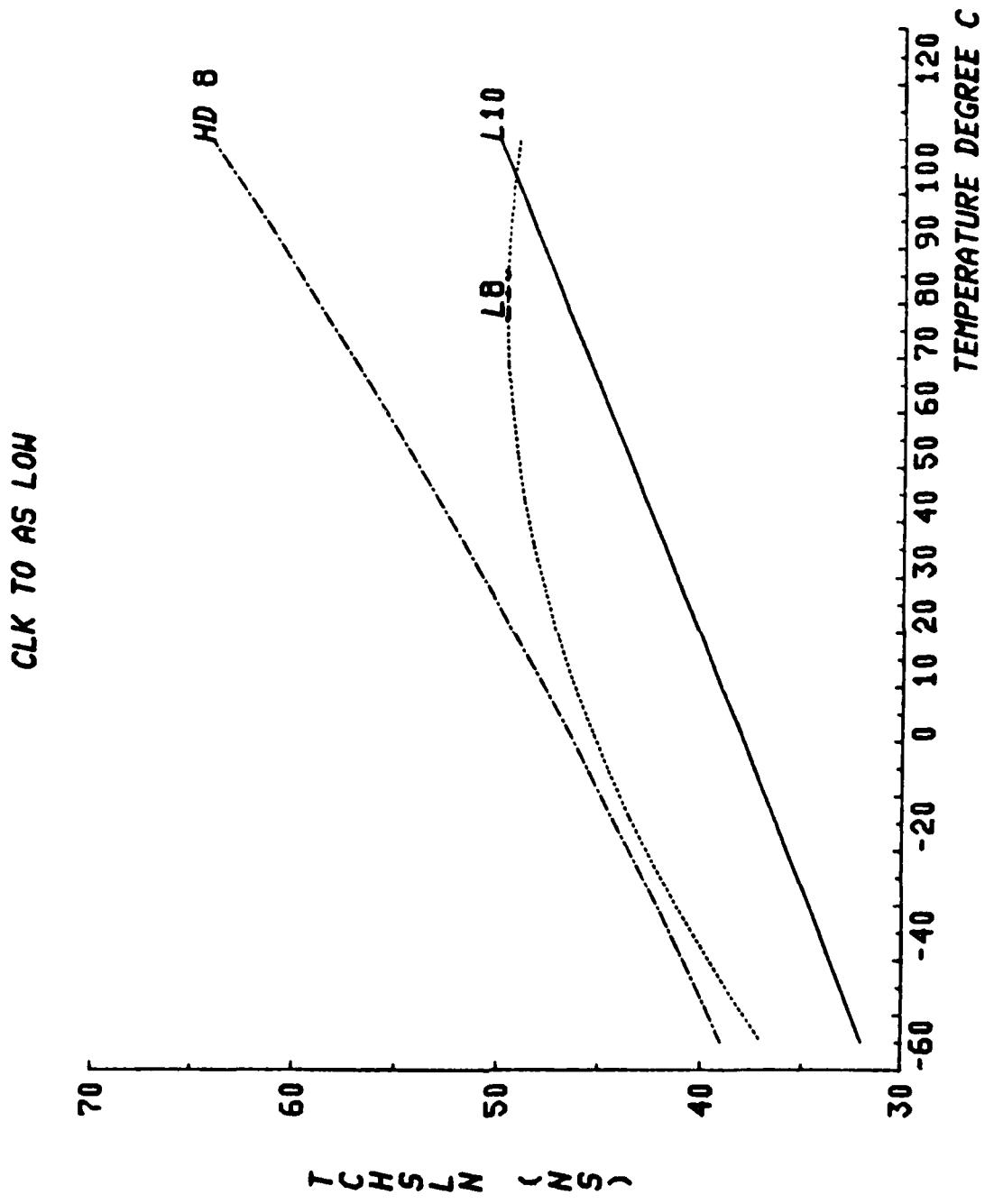


C-4

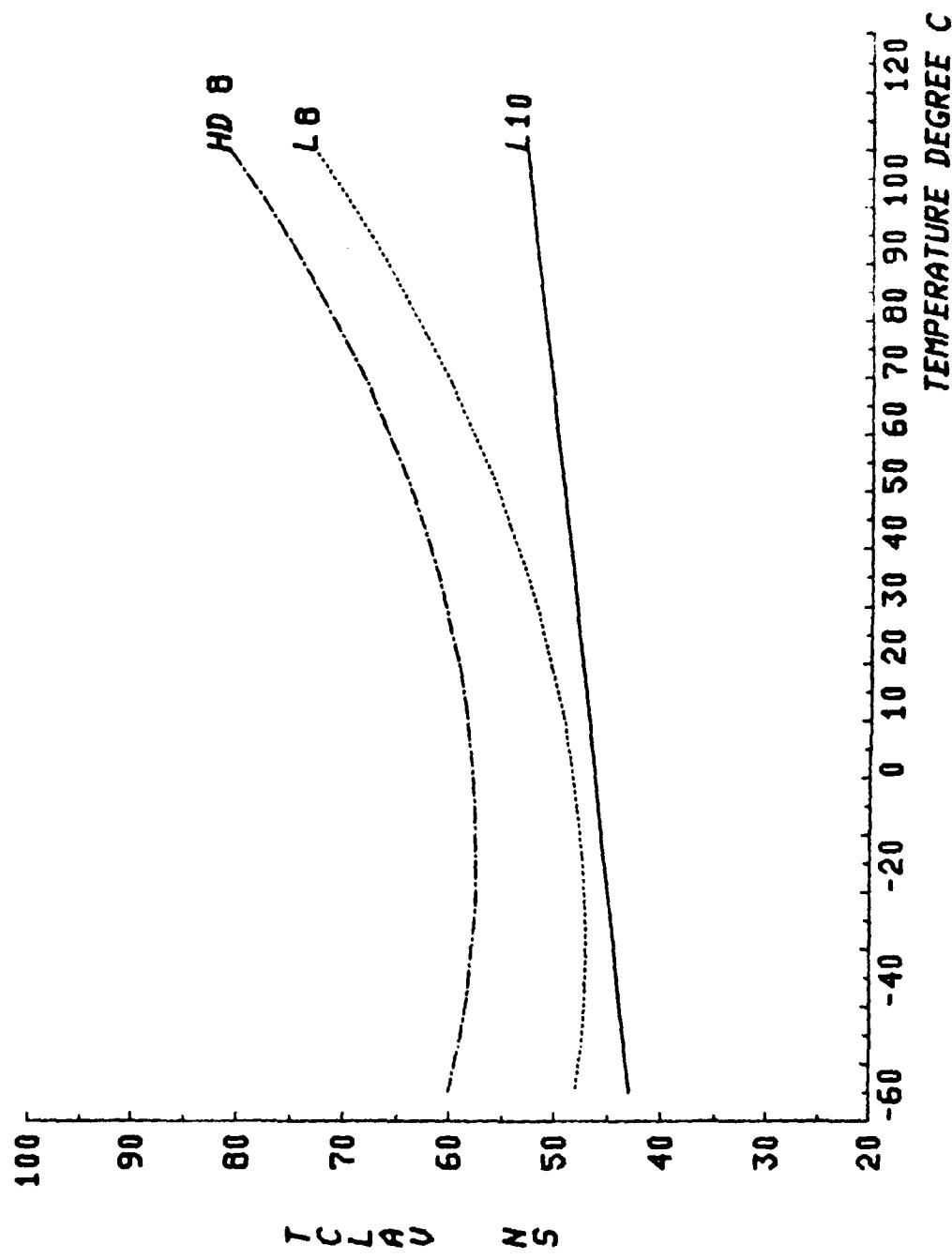
CLK TO R/W LOW



T C H R L A N S



CLK TO ADDRESS VALID



REFERENCES

1. Motorola Users Guide MC68000UM (AD)-(AD2)
2. Motorola Data Sheet AD1-814R2

MISSION
of
Rome Air Development Center

RADC plans and executes research, development, test and selected acquisition programs in support of Command, Control Communications and Intelligence (C³I) activities. Technical and engineering support within areas of technical competence is provided to ESD Program Offices (POs) and other ESD elements. The principal technical mission areas are communications, electromagnetic guidance and control, surveillance of ground and aerospace objects, intelligence data collection and handling, information system technology, ionospheric propagation, solid state sciences, microwave physics and electronic reliability, maintainability and compatibility.

03